ANALOG DEVICES

3-Axis, ±2 *g*/±4 *g*/±8 *g*/±16 *g* Digital Accelerometer

ADXL345

FEATURES

Ultralow power: as low as 40 µA in measurement mode and 0.1 µA in standby mode at V_S = 2.5 V (typical)
Power consumption scales automatically with bandwidth
User-selectable resolution
- **Fixed 10-bit resolution**
- **Full resolution, where resolution increases with *g* range, up to 13-bit resolution at ±16 *g* (maintaining 4 m*g*/LSB scale factor in all *g* ranges)**

Embedded, patent pending FIFO technology minimizes host processor load
Tap/double tap detection
Activity/inactivity monitoring
Free-fall detection
Supply voltage range: 2.0 V to 3.6 V
I/O voltage range: 1.7 V to V_S
SPI (3- and 4-wire) and I²C digital interfaces
Flexible interrupt modes mappable to either interrupt pin
Measurement ranges selectable via serial command
Bandwidth selectable via serial command
Wide temperature range (−40°C to +85°C)
10,000 *g* shock survival
Pb free/RoHS compliant
Small and thin: 3 mm × 5 mm × 1 mm LGA package

APPLICATIONS

Handsets
Medical instrumentation
Gaming and pointing devices
Industrial instrumentation
Personal navigation devices
Hard disk drive (HDD) protection
Fitness equipment

GENERAL DESCRIPTION

The ADXL345 is a small, thin, low power, 3-axis accelerometer with high resolution (13-bit) measurement at up to ±16 *g*. Digital output data is formatted as 16-bit twos complement and is accessible through either a SPI (3- or 4-wire) or I²C digital interface.

The ADXL345 is well suited for mobile device applications. It measures the static acceleration of gravity in tilt-sensing applications, as well as dynamic acceleration resulting from motion or shock. Its high resolution (4 m*g*/LSB) enables measurement of inclination changes less than 1.0°.

Several special sensing functions are provided. Activity and inactivity sensing detect the presence or lack of motion and if the acceleration on any axis exceeds a user-set level. Tap sensing detects single and double taps. Free-fall sensing detects if the device is falling. These functions can be mapped to one of two interrupt output pins. An integrated, patent pending 32-level first in, first out (FIFO) buffer can be used to store data to minimize host processor intervention.

Low power modes enable intelligent motion-based power management with threshold sensing and active acceleration measurement at extremely low power dissipation.

The ADXL345 is supplied in a small, thin, 3 mm × 5 mm × 1 mm, 14-lead, plastic package.

FUNCTIONAL BLOCK DIAGRAM

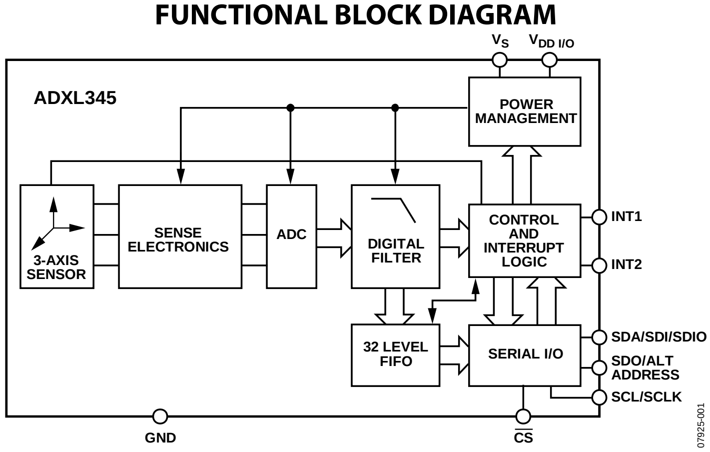

Figure 1.

Rev. 0

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REVISION HISTORY

5/09—Revision 0: Initial Version

SPECIFICATIONS

T_A = 25°C, V_S = 2.5 V, $V_{DD\ I/O}$ = 1.8 V, acceleration = 0 *g*, C_S = 1 µF tantalum, C_{IO} = 0.1 µF, unless otherwise noted.

Table 1. Specifications[1]

Parameter	Test Conditions	Min	Typ	Max	Unit
SENSOR INPUT	Each axis				
Measurement Range	User selectable		±2, ±4, ±8, ±16		*g*
Nonlinearity	Percentage of full scale		±0.5		%
Inter-Axis Alignment Error			±0.1		Degrees
Cross-Axis Sensitivity[2]			±1		%
OUTPUT RESOLUTION	Each axis				
All *g* Ranges	10-bit resolution		10		Bits
±2 *g* Range	Full resolution		10		Bits
±4 *g* Range	Full resolution		11		Bits
±8 *g* Range	Full resolution		12		Bits
±16 *g* Range	Full resolution		13		Bits
SENSITIVITY	Each axis				
Sensitivity at X_{OUT}, Y_{OUT}, Z_{OUT}	±2 *g*, 10-bit or full resolution	232	256	286	LSB/*g*
Scale Factor at X_{OUT}, Y_{OUT}, Z_{OUT}	±2 *g*, 10-bit or full resolution	3.5	3.9	4.3	m*g*/LSB
Sensitivity at X_{OUT}, Y_{OUT}, Z_{OUT}	±4 *g*, 10-bit resolution	116	128	143	LSB/*g*
Scale Factor at X_{OUT}, Y_{OUT}, Z_{OUT}	±4 *g*, 10-bit resolution	7.0	7.8	8.6	m*g*/LSB
Sensitivity at X_{OUT}, Y_{OUT}, Z_{OUT}	±8 *g*, 10-bit resolution	58	64	71	LSB/*g*
Scale Factor at X_{OUT}, Y_{OUT}, Z_{OUT}	±8 *g*, 10-bit resolution	14.0	15.6	17.2	m*g*/LSB
Sensitivity at X_{OUT}, Y_{OUT}, Z_{OUT}	±16 *g*, 10-bit resolution	29	32	36	LSB/*g*
Scale Factor at X_{OUT}, Y_{OUT}, Z_{OUT}	±16 *g*, 10-bit resolution	28.1	31.2	34.3	m*g*/LSB
Sensitivity Change Due to Temperature			±0.01		%/°C
0 *g* BIAS LEVEL	Each axis				
0 *g* Output for X_{OUT}, Y_{OUT}		−150	±40	+150	m*g*
0 *g* Output for Z_{OUT}		−250	±80	+250	m*g*
0 *g* Offset vs. Temperature for x-, y-Axes			±0.8		m*g*/°C
0 *g* Offset vs. Temperature for z-Axis			±4.5		m*g*/°C
NOISE PERFORMANCE					
Noise (x-, y-Axes)	Data rate = 100 Hz for ±2 *g*, 10-bit or full resolution		<1.0		LSB rms
Noise (z-Axis)	Data rate = 100 Hz for ±2 *g*, 10-bit or full resolution		<1.5		LSB rms
OUTPUT DATA RATE AND BANDWIDTH	User selectable				
Measurement Rate[3]		6.25		3200	Hz
SELF-TEST[4]	Data rate ≥ 100 Hz, 2.0 V ≤ V_S ≤ 3.6 V				
Output Change in x-Axis		0.20		2.10	*g*
Output Change in y-Axis		−2.10		−0.20	*g*
Output Change in z-Axis		0.30		3.40	*g*
POWER SUPPLY					
Operating Voltage Range (V_S)		2.0	2.5	3.6	V
Interface Voltage Range ($V_{DD\ I/O}$)	V_S ≤ 2.5 V	1.7	1.8	V_S	V
	V_S ≥ 2.5 V	2.0	2.5	V_S	V
Supply Current	Data rate > 100 Hz		145		µA
	Data rate < 10 Hz		40		µA
Standby Mode Leakage Current			0.1	2	µA
Turn-On Time[5]	Data rate = 3200 Hz		1.4		ms
TEMPERATURE					
Operating Temperature Range		−40		+85	°C
WEIGHT					
Device Weight			20		mg

[1] All minimum and maximum specifications are guaranteed. Typical specifications are not guaranteed.
[2] Cross-axis sensitivity is defined as coupling between any two axes.
[3] Bandwidth is half the output data rate.
[4] Self-test change is defined as the output (*g*) when the SELF_TEST bit = 1 (in the DATA_FORMAT register) minus the output (*g*) when the SELF_TEST bit = 0 (in the DATA_FORMAT register). Due to device filtering, the output reaches its final value after 4 × τ when enabling or disabling self-test, where τ = 1/(data rate).
[5] Turn-on and wake-up times are determined by the user-defined bandwidth. At a 100 Hz data rate, the turn-on and wake-up times are each approximately 11.1 ms. For other data rates, the turn-on and wake-up times are each approximately τ + 1.1 in milliseconds, where τ = 1/(data rate).

ABSOLUTE MAXIMUM RATINGS

Table 2.

Parameter	Rating
Acceleration	
Any Axis, Unpowered	10,000 *g*
Any Axis, Powered	10,000 *g*
V_S	−0.3 V to +3.6 V
$V_{DD\ I/O}$	−0.3 V to +3.6 V
Digital Pins	−0.3 V to $V_{DD\ I/O}$ + 0.3 V or 3.6 V, whichever is less
All Other Pins	−0.3 V to +3.6 V
Output Short-Circuit Duration (Any Pin to Ground)	Indefinite
Temperature Range	
Powered	−40°C to +105°C
Storage	−40°C to +105°C

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

THERMAL RESISTANCE

Table 3. Package Characteristics

Package Type	θ_{JA}	θ_{JC}	Device Weight
14-Terminal LGA	150°C/W	85°C/W	20 mg

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

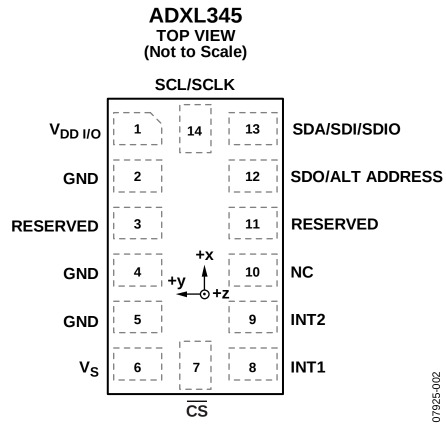

Figure 2. Pin Configuration

Table 4. Pin Function Descriptions

Pin No.	Mnemonic	Description
1	$V_{DD\ I/O}$	Digital Interface Supply Voltage.
2	GND	Must be connected to ground.
3	Reserved	Reserved. This pin must be connected to V_S or left open.
4	GND	Must be connected to ground.
5	GND	Must be connected to ground.
6	V_S	Supply Voltage.
7	$\overline{CS}$	Chip Select.
8	INT1	Interrupt 1 Output.
9	INT2	Interrupt 2 Output.
10	NC	Not Internally Connected.
11	Reserved	Reserved. This pin must be connected to ground or left open.
12	SDO/ALT ADDRESS	Serial Data Output/Alternate I^2C Address Select.
13	SDA/SDI/SDIO	Serial Data (I^2C)/Serial Data Input (SPI 4-Wire)/Serial Data Input and Output (SPI 3-Wire).
14	SCL/SCLK	Serial Communications Clock.

THEORY OF OPERATION

The ADXL345 is a complete 3-axis acceleration measurement system with a selectable measurement range of ±2 *g*, ±4 *g*, ±8 *g*, or ±16 *g*. It measures both dynamic acceleration resulting from motion or shock and static acceleration, such as gravity, which allows the device to be used as a tilt sensor.

The sensor is a polysilicon surface-micromachined structure built on top of a silicon wafer. Polysilicon springs suspend the structure over the surface of the wafer and provide a resistance against acceleration forces.

Deflection of the structure is measured using differential capacitors that consist of independent fixed plates and plates attached to the moving mass. Acceleration deflects the beam and unbalances the differential capacitor, resulting in a sensor output whose amplitude is proportional to acceleration. Phase-sensitive demodulation is used to determine the magnitude and polarity of the acceleration.

POWER SEQUENCING

Power can be applied to V_S or $V_{DD\ I/O}$ in any sequence without damaging the ADXL345. All possible power-on modes are summarized in Table 5. The interface voltage level is set with the interface supply voltage, $V_{DD\ I/O}$, which must be present to ensure that the ADXL345 does not create a conflict on the communication bus. For single-supply operation, $V_{DD\ I/O}$ can be the same as the main supply, V_S. In a dual-supply application, however, $V_{DD\ I/O}$ can differ from V_S to accommodate the desired interface voltage, as long as V_S is greater than $V_{DD\ I/O}$.

After V_S is applied, the device enters standby mode, where power consumption is minimized and the device waits for $V_{DD\ I/O}$ to be applied and for the command to enter measurement mode to be received. (This command can be initiated by setting the measure bit in the POWER_CTL register (Address 0x2D).) In addition, any register can be written to or read from to configure the part while the device is in standby mode. It is recommended to configure the device in standby mode and then to enable measurement mode. Clearing the measure bit returns the device to the standby mode.

Table 5. Power Sequencing

Condition	V_S	$V_{DD\ I/O}$	Description
Power Off	Off	Off	The device is completely off, but there is a potential for a communication bus conflict.
Bus Disabled	On	Off	The device is on in standby mode, but communication is unavailable and will create a conflict on the communication bus. The duration of this state should be minimized during power-up to prevent a conflict.
Bus Enabled	Off	On	No functions are available, but the device will not create a conflict on the communication bus.
Standby or Measurement	On	On	At power-up, the device is in standby mode, awaiting a command to enter measurement mode, and all sensor functions are off. After the device is instructed to enter measurement mode, all sensor functions are available.

POWER SAVINGS

Power Modes

The ADXL345 automatically modulates its power consumption in proportion to its output data rate, as outlined in Table 6. If additional power savings is desired, a lower power mode is available. In this mode, the internal sampling rate is reduced, allowing for power savings in the 12.5 Hz to 400 Hz data rate range but at the expense of slightly greater noise. To enter lower power mode, set the LOW_POWER bit (Bit 4) in the BW_RATE register (Address 0x2C). The current consumption in low power mode is shown in Table 7 for cases where there is an advantage for using low power mode. The current consumption values shown in Table 6 and Table 7 are for a V_S of 2.5 V. Current scales linearly with V_S.

Table 6. Current Consumption vs. Data Rate (T_A = 25°C, V_S = 2.5 V, $V_{DD\ I/O}$ = 1.8 V)

Output Data Rate (Hz)	Bandwidth (Hz)	Rate Code	I_{DD} (µA)
3200	1600	1111	145
1600	800	1110	100
800	400	1101	145
400	200	1100	145
200	100	1011	145
100	50	1010	145
50	25	1001	100
25	12.5	1000	65
12.5	6.25	0111	55
6.25	3.125	0110	40

Table 7. Current Consumption vs. Data Rate, Low Power Mode (T_A = 25°C, V_S = 2.5 V, $V_{DD\ I/O}$ = 1.8 V)

Output Data Rate (Hz)	Bandwidth (Hz)	Rate Code	I_{DD} (µA)
400	200	1100	100
200	100	1011	65
100	50	1010	55
50	25	1001	50
25	12.5	1000	40
12.5	6.25	0111	40

Auto Sleep Mode

Additional power can be saved if the ADXL345 automatically switches to sleep mode during periods of inactivity. To enable this feature, set the THRESH_INACT register (Address 0x25) and the TIME_INACT register (Address 0x26) each to a value that signifies inactivity (the appropriate value depends on the application), and then set the AUTO_SLEEP bit and the link bit in the POWER_CTL register (Address 0x2D). Current consumption at the sub-8 Hz data rates used in this mode is typically 40 µA for a V_S of 2.5 V.

Standby Mode

For even lower power operation, standby mode can be used. In standby mode, current consumption is reduced to 0.1 µA (typical). In this mode, no measurements are made. Standby mode is entered by clearing the measure bit (Bit 3) in the POWER_CTL register (Address 0x2D). Placing the device into standby mode preserves the contents of FIFO.

SERIAL COMMUNICATIONS

I^2C and SPI digital communications are available. In both cases, the ADXL345 operates as a slave. I^2C mode is enabled if the $\overline{CS}$ pin is tied high to $V_{DD\ I/O}$. The $\overline{CS}$ pin should always be tied high to $V_{DD\ I/O}$ or be driven by an external controller because there is no default mode if the $\overline{CS}$ pin is left unconnected. Therefore, not taking these precautions may result in an inability to communicate with the part. In SPI mode, the $\overline{CS}$ pin is controlled by the bus master. In both SPI and I^2C modes of operation, data transmitted from the ADXL345 to the master device should be ignored during writes to the ADXL345.

SPI

For SPI, either 3- or 4-wire configuration is possible, as shown in the connection diagrams in Figure 3 and Figure 4. Clearing the SPI bit in the DATA_FORMAT register (Address 0x31) selects 4-wire mode, whereas setting the SPI bit selects 3-wire mode. The maximum SPI clock speed is 5 MHz with 100 pF maximum loading, and the timing scheme follows clock polarity (CPOL) = 1 and clock phase (CPHA) = 1.

$\overline{CS}$ is the serial port enable line and is controlled by the SPI master. This line must go low at the start of a transmission and high at the end of a transmission, as shown in Figure 5. SCLK is the serial port clock and is supplied by the SPI master. It is stopped high when $\overline{CS}$ is high during a period of no transmission. SDI and SDO are the serial data input and output, respectively. Data should be sampled at the rising edge of SCLK.

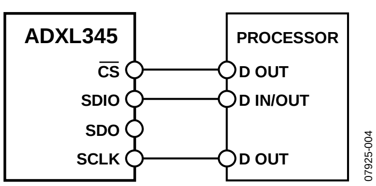

Figure 3. 3-Wire SPI Connection Diagram

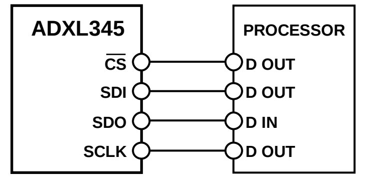

Figure 4. 4-Wire SPI Connection Diagram

To read or write multiple bytes in a single transmission, the multiple-byte bit, located after the R/$\overline{W}$ bit in the first byte transfer (MB in Figure 5 to Figure 7), must be set. After the register addressing and the first byte of data, each subsequent set of clock pulses (eight clock pulses) causes the ADXL345 to point to the next register for a read or write. This shifting continues until the clock pulses cease and $\overline{CS}$ is deasserted. To perform reads or writes on different, nonsequential registers, $\overline{CS}$ must be deasserted between transmissions and the new register must be addressed separately.

The timing diagram for 3-wire SPI reads or writes is shown in Figure 7. The 4-wire equivalents for SPI writes and reads are shown in Figure 5 and Figure 6, respectively.

Table 8. SPI Digital Input/Output Voltage

Parameter	Limit[1]	Unit
Digital Input Voltage		
Low Level Input Voltage (V_{IL})	$0.2 \times V_{DD\ I/O}$	V max
High Level Input Voltage (V_{IH})	$0.8 \times V_{DD\ I/O}$	V min
Digital Output Voltage		
Low Level Output Voltage (V_{OL})	$0.15 \times V_{DD\ I/O}$	V max
High Level Output Voltage (V_{OH})	$0.85 \times V_{DD\ I/O}$	V min

[1] Limits based on characterization results, not production tested.

Table 9. SPI Timing (T_A = 25°C, V_S = 2.5 V, $V_{DD\ I/O}$ = 1.8 V)[1]

Parameter	Limit[2, 3] Min	Max	Unit	Description
f_{SCLK}		5	MHz	SPI clock frequency
t_{SCLK}	200		ns	1/(SPI clock frequency) mark-space ratio for the SCLK input is 40/60 to 60/40
t_{DELAY}	10		ns	$\overline{CS}$ falling edge to SCLK falling edge
t_{QUIET}	10		ns	SCLK rising edge to $\overline{CS}$ rising edge
t_{DIS}		100	ns	$\overline{CS}$ rising edge to SDO disabled
$t_{CS,DIS}$	250		ns	$\overline{CS}$ deassertion between SPI communications
t_S	$0.4 \times t_{SCLK}$		ns	SCLK low pulse width (space)
t_M	$0.4 \times t_{SCLK}$		ns	SCLK high pulse width (mark)
t_{SDO}		95	ns	SCLK falling edge to SDO transition
t_{SETUP}	10		ns	SDI valid before SCLK rising edge
t_{HOLD}	10		ns	SDI valid after SCLK rising edge

[1] The $\overline{CS}$, SCLK, SDI, and SDO pins are not internally pulled up or down; they must be driven for proper operation.
[2] Limits based on characterization results, characterized with f_{SCLK} = 5 MHz and bus load capacitance of 100 pF; not production tested.
[3] The timing values are measured corresponding to the input thresholds (V_{IL} and V_{IH}) given in Table 8.

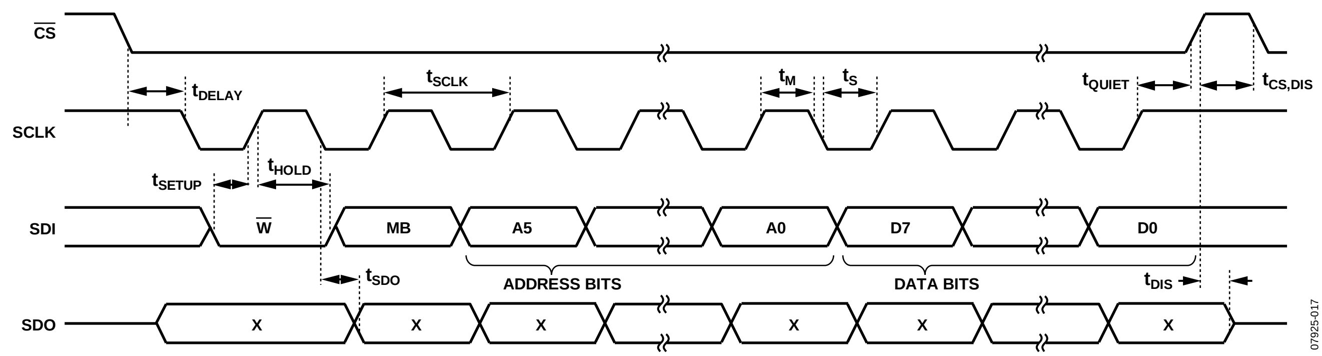

Figure 5. SPI 4-Wire Write

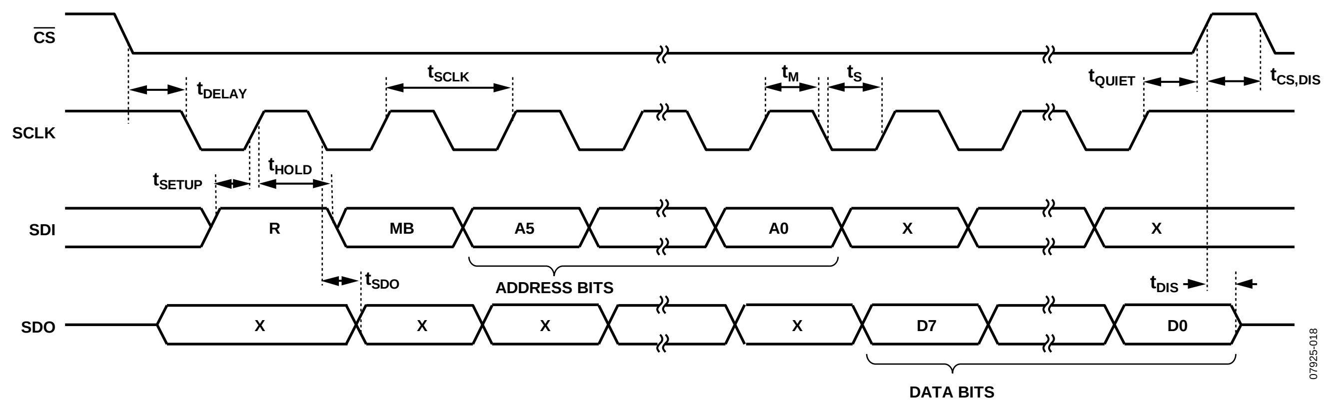

Figure 6. SPI 4-Wire Read

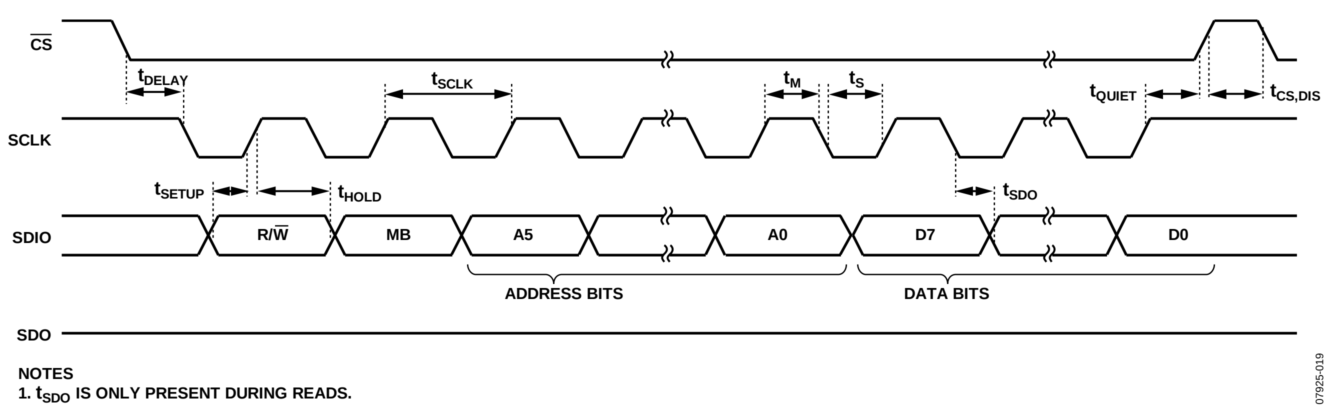

Figure 7. SPI 3-Wire Read/Write

I²C

With $\overline{CS}$ tied high to $V_{DD\ I/O}$, the ADXL345 is in I²C mode, requiring a simple 2-wire connection as shown in Figure 8. The ADXL345 conforms to the *UM10204 I²C-Bus Specification and User Manual*, Rev. 03—19 June 2007, available from NXP Semiconductor. It supports standard (100 kHz) and fast (400 kHz) data transfer modes if the timing parameters given in Table 11 and Figure 10 are met. Single- or multiple-byte reads/writes are supported, as shown in Figure 9. With the SDO/ALT ADDRESS pin high, the 7-bit I²C address for the device is 0x1D, followed by the R/$\overline{W}$ bit. This translates to 0x3A for a write and 0x3B for a read. An alternate I²C address of 0x53 (followed by the R/$\overline{W}$ bit) can be chosen by grounding the SDO/ALT ADDRESS pin (Pin 12). This translates to 0xA6 for a write and 0xA7 for a read.

If other devices are connected to the same I²C bus, the nominal operating voltage level of these other devices cannot exceed $V_{DD\ I/O}$ by more than 0.3 V. External pull-up resistors, R_P, are necessary for proper I²C operation. Refer to the *UM10204 I²C-Bus Specification and User Manual*, Rev. 03—19 June 2007, when selecting pull-up resistor values to ensure proper operation.

Table 10. I²C Digital Input/Output Voltage

Parameter	Limit[1]	Unit
Digital Input Voltage		
Low Level Input Voltage (V_{IL})	$0.25 \times V_{DD\ I/O}$	V max
High Level Input Voltage (V_{IH})	$0.75 \times V_{DD\ I/O}$	V min
Digital Output Voltage		
Low Level Output Voltage (V_{OL})[2]	$0.2 \times V_{DD\ I/O}$	V max

[1] Limits based on characterization results; not production tested.
[2] The limit given is only for $V_{DD\ I/O} < 2$ V. When $V_{DD\ I/O} > 2$ V, the limit is 0.4 V max.

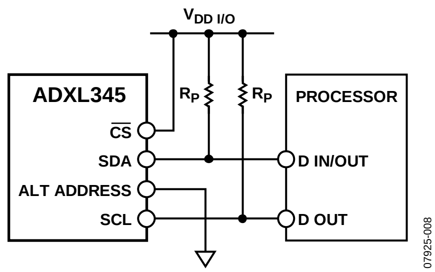

Figure 8. I²C Connection Diagram (Address 0x53)

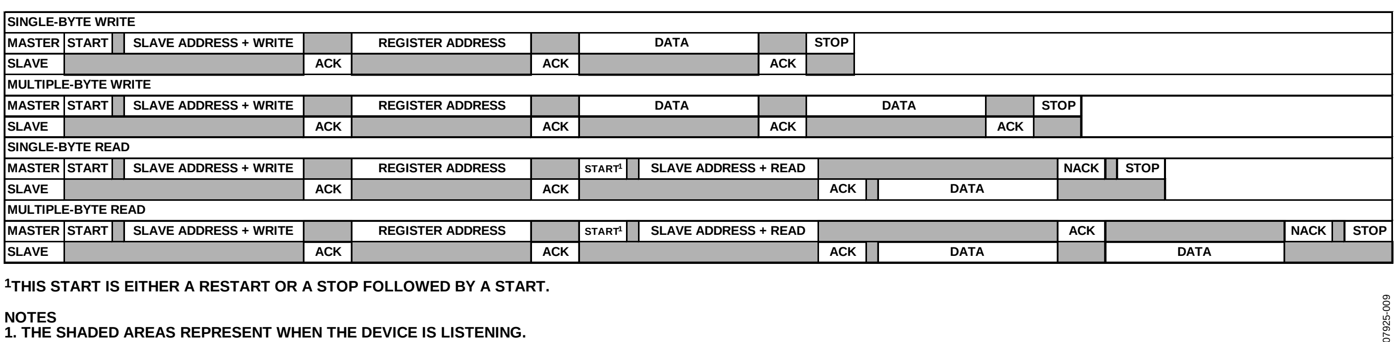

Figure 9. I²C Device Addressing

Table 11. I²C Timing (T_A = 25°C, V_S = 2.5 V, $V_{DD\ I/O}$ = 1.8 V)

Parameter	Limit[1, 2] Min	Max	Unit	Description
f_{SCL}		400	kHz	SCL clock frequency
t_1	2.5		µs	SCL cycle time
t_2	0.6		µs	t_{HIGH}, SCL high time
t_3	1.3		µs	t_{LOW}, SCL low time
t_4	0.6		µs	$t_{HD,\ STA}$, start/repeated start condition hold time
t_5	350		ns	$t_{SU,\ DAT}$, data setup time
t_6[3, 4, 5, 6]	0	0.65	µs	$t_{HD,\ DAT}$, data hold time
t_7	0.6		µs	$t_{SU,\ STA}$, setup time for repeated start
t_8	0.6		µs	$t_{SU,\ STO}$, stop condition setup time
t_9	1.3		µs	t_{BUF}, bus-free time between a stop condition and a start condition
t_{10}		300	ns	t_R, rise time of both SCL and SDA when receiving
	0		ns	t_R, rise time of both SCL and SDA when receiving or transmitting
t_{11}		250	ns	t_F, fall time of SDA when receiving
		300	ns	t_F, fall time of both SCL and SDA when transmitting
	20 + 0.1 C_b[7]		ns	t_F, fall time of both SCL and SDA when transmitting or receiveing
C_b		400	pF	Capacitive load for each bus line

[1] Limits based on characterization results, with f_{SCL} = 400 kHz and a 3 mA sink current; not production tested.
[2] All values referred to the V_{IH} and the V_{IL} levels given in Table 10.
[3] t_6 is the data hold time that is measured from the falling edge of SCL. It applies to data in transmission and acknowledge times.
[4] A transmitting device must internally provide an output hold time of at least 300 ns for the SDA signal (with respect to $V_{IH(min)}$ of the SCL signal) to bridge the undefined region of the falling edge of SCL.
[5] The maximum t_6 value must be met only if the device does not stretch the low period (t_3) of the SCL signal.
[6] The maximum value for t_6 is a function of the clock low time (t_3), the clock rise time (t_{10}), and the minimum data setup time ($t_{5(min)}$). This value is calculated as $t_{6(max)} = t_3 - t_{10} - t_{5(min)}$.
[7] C_b is the total capacitance of one bus line in picofarads.

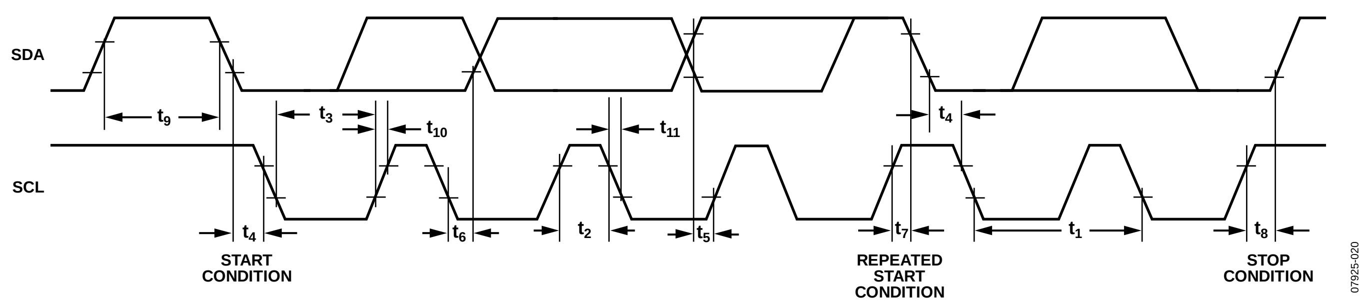

Figure 10. I²C Timing Diagram

INTERRUPTS

The ADXL345 provides two output pins for driving interrupts: INT1 and INT2. Each interrupt function is described in detail in this section. All functions can be used simultaneously, with the only limiting feature being that some functions may need to share interrupt pins. Interrupts are enabled by setting the appropriate bit in the INT_ENABLE register (Address 0x2E) and are mapped to either the INT1 or INT2 pin based on the contents of the INT_MAP register (Address 0x2F). It is recommended that interrupt bits be configured with the interrupts disabled, preventing interrupts from being accidentally triggered during configuration. This can be done by writing a value of 0x00 to the INT_ENABLE register. Clearing interrupts is performed either by reading the data registers (Address 0x32 to Address 0x37) until the interrupt condition is no longer valid for the data-related interrupts or by reading the INT_SOURCE register (Address 0x30) for the remaining interrupts. This section describes the interrupts that can be set in the INT_ENABLE register and monitored in the INT_SOURCE register.

DATA_READY

The DATA_READY bit is set when new data is available and is cleared when no new data is available.

SINGLE_TAP

The SINGLE_TAP bit is set when a single acceleration event that is greater than the value in the THRESH_TAP register (Address 0x1D) occurs for less time than is specified in the DUR register (Address 0x21).

DOUBLE_TAP

The DOUBLE_TAP bit is set when two acceleration events that are greater than the value in the THRESH_TAP register (Address 0x1D) occur for less time than is specified in the DUR register (Address 0x21), with the second tap starting after the time specified by the latent register (Address 0x22) but within the time specified in the window register (Address 0x23). See the Tap Detection section for more details.

Activity

The activity bit is set when acceleration greater than the value stored in the THRESH_ACT register (Address 0x24) is experienced.

Inactivity

The inactivity bit is set when acceleration of less than the value stored in the THRESH_INACT register (Address 0x25) is experienced for more time than is specified in the TIME_INACT register (Address 0x26). The maximum value for TIME_INACT is 255 sec.

FREE_FALL

The FREE_FALL bit is set when acceleration of less than the value stored in the THRESH_FF register (Address 0x28) is experienced for more time than is specified in the TIME_FF register (Address 0x29). The FREE_FALL interrupt differs from the inactivity interrupt as follows: all axes always participate, the timer period is much smaller (1.28 sec maximum), and the mode of operation is always dc-coupled.

Watermark

The watermark bit is set when the number of samples in FIFO equals the value stored in the samples bits (Register FIFO_CTL, Address 0x38). The watermark bit is cleared automatically when FIFO is read, and the content returns to a value below the value stored in the samples bits.

Overrun

The overrun bit is set when new data replaces unread data. The precise operation of the overrun function depends on the FIFO mode. In bypass mode, the overrun bit is set when new data replaces unread data in the DATAX, DATAY, and DATAZ registers (Address 0x32 to Address 0x37). In all other modes, the overrun bit is set when FIFO is filled. The overrun bit is automatically cleared when the contents of FIFO are read.

FIFO

The ADXL345 contains patent pending technology for an embedded 32-level FIFO that can be used to minimize host processor burden. This buffer has four modes: bypass, FIFO, stream, and trigger (see Table 19). Each mode is selected by the settings of the FIFO_MODE bits in the FIFO_CTL register (Address 0x38).

Bypass Mode

In bypass mode, FIFO is not operational and, therefore, remains empty.

FIFO Mode

In FIFO mode, data from measurements of the x-, y-, and z-axes are stored in FIFO. When the number of samples in FIFO equals the level specified in the samples bits of the FIFO_CTL register (Address 0x38), the watermark interrupt is set. FIFO continues accumulating samples until it is full (32 samples from measurements of the x-, y-, and z-axes) and then stops collecting data. After FIFO stops collecting data, the device continues to operate; therefore, features such as tap detection can be used after FIFO is full. The watermark interrupt continues to occur until the number of samples in FIFO is less than the value stored in the samples bits of the FIFO_CTL register.

Stream Mode

In stream mode, data from measurements of the x-, y-, and z-axes are stored in FIFO. When the number of samples in FIFO equals the level specified in the samples bits of the FIFO_CTL register (Address 0x38), the watermark interrupt is set. FIFO continues accumulating samples and holds the latest 32 samples from measurements of the x-, y-, and z-axes, discarding older data as new data arrives. The watermark interrupt continues occurring until the number of samples in FIFO is less than the value stored in the samples bits of the FIFO_CTL register.

Trigger Mode

In trigger mode, FIFO accumulates samples, holding the latest 32 samples from measurements of the x-, y-, and z-axes. After a trigger event occurs and an interrupt is sent to the INT1 or INT2 pin (determined by the trigger bit in the FIFO_CTL register), FIFO keeps the last n samples (where n is the value specified by the samples bits in the FIFO_CTL register) and then operates in FIFO mode, collecting new samples only when FIFO is not full. A delay of at least 5 μs should be present between the trigger event occurring and the start of reading data from the FIFO to allow the FIFO to discard and retain the necessary samples. Additional trigger events cannot be recognized until the trigger mode is reset. To reset the trigger mode, set the device to bypass mode and then set the device back to trigger mode. Note that the FIFO data should be read first because placing the device into bypass mode clears FIFO.

Retrieving Data from FIFO

The FIFO data is read through the DATAX, DATAY, and DATAZ registers (Address 0x32 to Address 0x37). When the FIFO is in FIFO, stream, or trigger mode, reads to the DATAX, DATAY, and DATAZ registers read data stored in the FIFO. Each time data is read from the FIFO, the oldest x-, y-, and z-axes data are placed into the DATAX, DATAY and DATAZ registers.

If a single-byte read operation is performed, the remaining bytes of data for the current FIFO sample are lost. Therefore, all axes of interest should be read in a burst (or multiple-byte) read operation. To ensure that the FIFO has completely popped (that is, that new data has completely moved into the DATAX, DATAY, and DATAZ registers), there must be at least 5 μs between the end of reading the data registers and the start of a new read of the FIFO or a read of the FIFO_STATUS register (Address 0x39). The end of reading a data register is signified by the transition from Register 0x37 to Register 0x38 or by the $\overline{CS}$ pin going high.

For SPI operation at 1.6 MHz or less, the register addressing portion of the transmission is a sufficient delay to ensure that the FIFO has completely popped. For SPI operation greater than 1.6 MHz, it is necessary to deassert the $\overline{CS}$ pin to ensure a total delay of 5 μs; otherwise, the delay will not be sufficient. The total delay necessary for 5 MHz operation is at most 3.4 μs. This is not a concern when using I^2C mode because the communication rate is low enough to ensure a sufficient delay between FIFO reads.

SELF-TEST

The ADXL345 incorporates a self-test feature that effectively tests its mechanical and electronic systems simultaneously. When the self-test function is enabled (via the SELF_TEST bit in the DATA_FORMAT register, Address 0x31), an electrostatic force is exerted on the mechanical sensor. This electrostatic force moves the mechanical sensing element in the same manner as acceleration, and it is additive to the acceleration experienced by the device. This added electrostatic force results in an output change in the x-, y-, and z-axes. Because the electrostatic force is proportional to V_S^2, the output change varies with V_S. The self-test feature of the ADXL345 also exhibits a bimodal behavior that depends on which phase of the clock self-test is enabled. However, the limits shown in Table 1 and Table 12 to Table 15 are valid for all potential self-test values across the entire allowable voltage range. Use of the self-test feature at data rates less than 100 Hz may yield values outside these limits. Therefore, the part should be placed into a data rate of 100 Hz or greater when using self-test.

Table 12. Self-Test Output in LSB for ±2 *g*, Full Resolution

Axis	Min	Max	Unit
X	50	540	LSB
Y	−540	−50	LSB
Z	75	875	LSB

Table 13. Self-Test Output in LSB for ±4 *g*, 10-Bit Resolution

Axis	Min	Max	Unit
X	25	270	LSB
Y	−270	−25	LSB
Z	38	438	LSB

Table 14. Self-Test Output in LSB for ±8 *g*, 10-Bit Resolution

Axis	Min	Max	Unit
X	12	135	LSB
Y	−135	−12	LSB
Z	19	219	LSB

Table 15. Self-Test Output in LSB for ±16 *g*, 10-Bit Resolution

Axis	Min	Max	Unit
X	6	67	LSB
Y	−67	−6	LSB
Z	10	110	LSB

REGISTER MAP

Table 16. Register Map

Address					
Hex	**Dec**	**Name**	**Type**	**Reset Value**	**Description**
0x00	0	DEVID	R	11100101	Device ID.
0x01 to 0x01C	1 to 28	Reserved			Reserved. Do not access.
0x1D	29	THRESH_TAP	R/$\overline{W}$	00000000	Tap threshold.
0x1E	30	OFSX	R/$\overline{W}$	00000000	X-axis offset.
0x1F	31	OFSY	R/$\overline{W}$	00000000	Y-axis offset.
0x20	32	OFSZ	R/$\overline{W}$	00000000	Z-axis offset.
0x21	33	DUR	R/$\overline{W}$	00000000	Tap duration.
0x22	34	Latent	R/$\overline{W}$	00000000	Tap latency.
0x23	35	Window	R/$\overline{W}$	00000000	Tap window.
0x24	36	THRESH_ACT	R/$\overline{W}$	00000000	Activity threshold.
0x25	37	THRESH_INACT	R/$\overline{W}$	00000000	Inactivity threshold.
0x26	38	TIME_INACT	R/$\overline{W}$	00000000	Inactivity time.
0x27	39	ACT_INACT_CTL	R/$\overline{W}$	00000000	Axis enable control for activity and inactivity detection.
0x28	40	THRESH_FF	R/$\overline{W}$	00000000	Free-fall threshold.
0x29	41	TIME_FF	R/$\overline{W}$	00000000	Free-fall time.
0x2A	42	TAP_AXES	R/$\overline{W}$	00000000	Axis control for tap/double tap.
0x2B	43	ACT_TAP_STATUS	R	00000000	Source of tap/double tap.
0x2C	44	BW_RATE	R/$\overline{W}$	00001010	Data rate and power mode control.
0x2D	45	POWER_CTL	R/$\overline{W}$	00000000	Power-saving features control.
0x2E	46	INT_ENABLE	R/$\overline{W}$	00000000	Interrupt enable control.
0x2F	47	INT_MAP	R/$\overline{W}$	00000000	Interrupt mapping control.
0x30	48	INT_SOURCE	R	00000010	Source of interrupts.
0x31	49	DATA_FORMAT	R/$\overline{W}$	00000000	Data format control.
0x32	50	DATAX0	R	00000000	X-Axis Data 0.
0x33	51	DATAX1	R	00000000	X-Axis Data 1.
0x34	52	DATAY0	R	00000000	Y-Axis Data 0.
0x35	53	DATAY1	R	00000000	Y-Axis Data 1.
0x36	54	DATAZ0	R	00000000	Z-Axis Data 0.
0x37	55	DATAZ1	R	00000000	Z-Axis Data 1.
0x38	56	FIFO_CTL	R/$\overline{W}$	00000000	FIFO control.
0x39	57	FIFO_STATUS	R	00000000	FIFO status.

REGISTER DEFINITIONS

Register 0x00—DEVID (Read Only)

D7	D6	D5	D4	D3	D2	D1	D0
1	1	1	0	0	1	0	1

The DEVID register holds a fixed device ID code of 0xE5 (345 octal).

Register 0x1D—THRESH_TAP (Read/Write)

The THRESH_TAP register is eight bits and holds the threshold value for tap interrupts. The data format is unsigned, so the magnitude of the tap event is compared with the value in THRESH_TAP. The scale factor is 62.5 m*g*/LSB (that is, 0xFF = +16 *g*). A value of 0 may result in undesirable behavior if tap/double tap interrupts are enabled.

Register 0x1E, Register 0x1F, Register 0x20—OFSX, OFSY, OFSZ (Read/Write)

The OFSX, OFSY, and OFSZ registers are each eight bits and offer user-set offset adjustments in twos complement format with a scale factor of 15.6 m*g*/LSB (that is, 0x7F = +2 *g*).

Register 0x21—DUR (Read/Write)

The DUR register is eight bits and contains an unsigned time value representing the maximum time that an event must be above the THRESH_TAP threshold to qualify as a tap event. The scale factor is 625 µs/LSB. A value of 0 disables the tap/double tap functions.

Register 0x22—Latent (Read/Write)

The latent register is eight bits and contains an unsigned time value representing the wait time from the detection of a tap event to the start of the time window (defined by the window register) during which a possible second tap event can be detected. The scale factor is 1.25 ms/LSB. A value of 0 disables the double tap function.

Register 0x23—Window (Read/Write)

The window register is eight bits and contains an unsigned time value representing the amount of time after the expiration of the latency time (determined by the latent register) during which a second valid tap can begin. The scale factor is 1.25 ms/LSB. A value of 0 disables the double tap function.

Register 0x24—THRESH_ACT (Read/Write)

The THRESH_ACT register is eight bits and holds the threshold value for detecting activity. The data format is unsigned, so the magnitude of the activity event is compared with the value in the THRESH_ACT register. The scale factor is 62.5 m*g*/LSB. A value of 0 may result in undesirable behavior if the activity interrupt is enabled.

Register 0x25—THRESH_INACT (Read/Write)

The THRESH_INACT register is eight bits and holds the threshold value for detecting inactivity. The data format is unsigned, so the magnitude of the inactivity event is compared with the value in the THRESH_INACT register. The scale factor is 62.5 m*g*/LSB. A value of 0 m*g* may result in undesirable behavior if the inactivity interrupt is enabled.

Register 0x26—TIME_INACT (Read/Write)

The TIME_INACT register is eight bits and contains an unsigned time value representing the amount of time that acceleration must be less than the value in the THRESH_INACT register for inactivity to be declared. The scale factor is 1 sec/LSB. Unlike the other interrupt functions, which use unfiltered data (see the Threshold section), the inactivity function uses filtered output data. At least one output sample must be generated for the inactivity interrupt to be triggered. This results in the function appearing unresponsive if the TIME_INACT register is set to a value less than the time constant of the output data rate. A value of 0 results in an interrupt when the output data is less than the value in the THRESH_INACT register.

Register 0x27—ACT_INACT_CTL (Read/Write)

D7	D6	D5	D4
ACT ac/dc	ACT_X enable	ACT_Y enable	ACT_Z enable
D3	**D2**	**D1**	**D0**
INACT ac/dc	INACT_X enable	INACT_Y enable	INACT_Z enable

ACT AC/DC and INACT AC/DC Bits

A setting of 0 selects dc-coupled operation, and a setting of 1 enables ac-coupled operation. In dc-coupled operation, the current acceleration magnitude is compared directly with THRESH_ACT and THRESH_INACT to determine whether activity or inactivity is detected.

In ac-coupled operation for activity detection, the acceleration value at the start of activity detection is taken as a reference value. New samples of acceleration are then compared to this reference value, and if the magnitude of the difference exceeds the THRESH_ACT value, the device triggers an activity interrupt.

Similarly, in ac-coupled operation for inactivity detection, a reference value is used for comparison and is updated whenever the device exceeds the inactivity threshold. After the reference value is selected, the device compares the magnitude of the difference between the reference value and the current acceleration with THRESH_INACT. If the difference is less than the value in THRESH_INACT for the time in TIME_INACT, the device is considered inactive and the inactivity interrupt is triggered.

ACT_x Enable Bits and INACT_x Enable Bits

A setting of 1 enables x-, y-, or z-axis participation in detecting activity or inactivity. A setting of 0 excludes the selected axis from participation. If all axes are excluded, the function is disabled.

Register 0x28—THRESH_FF (Read/Write)

The THRESH_FF register is eight bits and holds the threshold value, in unsigned format, for free-fall detection. The root-sum-square (RSS) value of all axes is calculated and compared with the value in THRESH_FF to determine if a free-fall event occurred. The scale factor is 62.5 m*g*/LSB. Note that a value of 0 m*g* may result in undesirable behavior if the free-fall interrupt is enabled. Values between 300 m*g* and 600 m*g* (0x05 to 0x09) are recommended.

Register 0x29—TIME_FF (Read/Write)

The TIME_FF register is eight bits and stores an unsigned time value representing the minimum time that the RSS value of all axes must be less than THRESH_FF to generate a free-fall interrupt. The scale factor is 5 ms/LSB. A value of 0 may result in undesirable behavior if the free-fall interrupt is enabled. Values between 100 ms and 350 ms (0x14 to 0x46) are recommended.

Register 0x2A—TAP_AXES (Read/Write)

D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	Suppress	TAP_X enable	TAP_Y enable	TAP_Z enable

Suppress Bit

Setting the suppress bit suppresses double tap detection if acceleration greater than the value in THRESH_TAP is present between taps. See the Tap Detection section for more details.

TAP_x Enable Bits

A setting of 1 in the TAP_X enable, TAP_Y enable, or TAP_Z enable bit enables x-, y-, or z-axis participation in tap detection. A setting of 0 excludes the selected axis from participation in tap detection.

Register 0x2B—ACT_TAP_STATUS (Read Only)

D7	D6	D5	D4	D3	D2	D1	D0
0	ACT_X source	ACT_Y source	ACT_Z source	Asleep	TAP_X source	TAP_Y source	TAP_Z source

ACT_x Source and TAP_x Source Bits

These bits indicate the first axis involved in a tap or activity event. A setting of 1 corresponds to involvement in the event, and a setting of 0 corresponds to no involvement. When new data is available, these bits are not cleared but are overwritten by the new data. The ACT_TAP_STATUS register should be read before clearing the interrupt. Disabling an axis from participation clears the corresponding source bit when the next activity or tap/double tap event occurs.

Asleep Bit

A setting of 1 in the asleep bit indicates that the part is asleep, and a setting of 0 indicates that the part is not asleep. See the Register 0x2D—POWER_CTL (Read/Write) section for more information on autosleep mode.

Register 0x2C—BW_RATE (Read/Write)

D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	LOW_POWER	Rate			

LOW_POWER Bit

A setting of 0 in the LOW_POWER bit selects normal operation, and a setting of 1 selects reduced power operation, which has somewhat higher noise (see the Power Modes section for details).

Rate Bits

These bits select the device bandwidth and output data rate (see Table 6 and Table 7 for details). The default value is 0x0A, which translates to a 100 Hz output data rate. An output data rate should be selected that is appropriate for the communication protocol and frequency selected. Selecting too high of an output data rate with a low communication speed results in samples being discarded.

Register 0x2D—POWER_CTL (Read/Write)

D7	D6	D5	D4	D3	D2	D1	D0
0	0	Link	AUTO_SLEEP	Measure	Sleep	Wakeup	

Link Bit

A setting of 1 in the link bit with both the activity and inactivity functions enabled delays the start of the activity function until inactivity is detected. After activity is detected, inactivity detection begins, preventing the detection of activity. This bit serially links the activity and inactivity functions. When this bit is set to 0, the inactivity and activity functions are concurrent. Additional information can be found in the Link Mode section.

When clearing the link bit, it is recommended that the part be placed into standby mode and then set back to measurement mode with a subsequent write. This is done to ensure that the device is properly biased if sleep mode is manually disabled; otherwise, the first few samples of data after the link bit is cleared may have additional noise, especially if the device was asleep when the bit was cleared.

AUTO_SLEEP Bit

If the link bit is set, a setting of 1 in the AUTO_SLEEP bit sets the ADXL345 to switch to sleep mode when inactivity is detected (that is, when acceleration has been below the THRESH_INACT value for at least the time indicated by TIME_INACT). A setting of 0 disables automatic switching to sleep mode. See the description of the sleep bit in this section for more information.

When clearing the AUTO_SLEEP bit, it is recommended that the part be placed into standby mode and then set back to measurement mode with a subsequent write. This is done to ensure that the device is properly biased if sleep mode is manually disabled; otherwise, the first few samples of data after the AUTO_SLEEP bit is cleared may have additional noise, especially if the device was asleep when the bit was cleared.

Measure Bit

A setting of 0 in the measure bit places the part into standby mode, and a setting of 1 places the part into measurement mode. The ADXL345 powers up in standby mode with minimum power consumption.

Sleep Bit

A setting of 0 in the sleep bit puts the part into the normal mode of operation, and a setting of 1 places the part into sleep mode. Sleep mode suppresses DATA_READY, stops transmission of data to FIFO, and switches the sampling rate to one specified by the wakeup bits. In sleep mode, only the activity function can be used.

When clearing the sleep bit, it is recommended that the part be placed into standby mode and then set back to measurement mode with a subsequent write. This is done to ensure that the device is properly biased if sleep mode is manually disabled; otherwise, the first few samples of data after the sleep bit is cleared may have additional noise, especially if the device was asleep when the bit was cleared.

Wakeup Bits

These bits control the frequency of readings in sleep mode as described in Table 17.

Table 17. Frequency of Readings in Sleep Mode

Setting		
D1	**D0**	**Frequency (Hz)**
0	0	8
0	1	4
1	0	2
1	1	1

Register 0x2E—INT_ENABLE (Read/Write)

D7	D6	D5	D4
DATA_READY	SINGLE_TAP	DOUBLE_TAP	Activity
D3	**D2**	**D1**	**D0**
Inactivity	FREE_FALL	Watermark	Overrun

Setting bits in this register to a value of 1 enables their respective functions to generate interrupts, whereas a value of 0 prevents the functions from generating interrupts. The DATA_READY, watermark, and overrun bits enable only the interrupt output; the functions are always enabled. It is recommended that interrupts be configured before enabling their outputs.

Register 0x2F—INT_MAP (Read/Write)

D7	D6	D5	D4
DATA_READY	SINGLE_TAP	DOUBLE_TAP	Activity
D3	**D2**	**D1**	**D0**
Inactivity	FREE_FALL	Watermark	Overrun

Any bits set to 0 in this register send their respective interrupts to the INT1 pin, whereas bits set to 1 send their respective interrupts to the INT2 pin. All selected interrupts for a given pin are OR'ed.

Register 0x30—INT_SOURCE (Read Only)

D7	D6	D5	D4
DATA_READY	SINGLE_TAP	DOUBLE_TAP	Activity
D3	**D2**	**D1**	**D0**
Inactivity	FREE_FALL	Watermark	Overrun

Bits set to 1 in this register indicate that their respective functions have triggered an event, whereas a value of 0 indicates that the corresponding event has not occurred. The DATA_READY, watermark, and overrun bits are always set if the corresponding events occur, regardless of the INT_ENABLE register settings, and are cleared by reading data from the DATAX, DATAY, and DATAZ registers. The DATA_READY and watermark bits may require multiple reads, as indicated in the FIFO mode descriptions in the FIFO section. Other bits, and the corresponding interrupts, are cleared by reading the INT_SOURCE register.

Register 0x31—DATA_FORMAT (Read/Write)

D7	D6	D5	D4	D3	D2	D1	D0
SELF_TEST	SPI	INT_INVERT	0	FULL_RES	Justify	Range	

The DATA_FORMAT register controls the presentation of data to Register 0x32 through Register 0x37. All data, except that for the ±16 *g* range, must be clipped to avoid rollover.

SELF_TEST Bit

A setting of 1 in the SELF_TEST bit applies a self-test force to the sensor, causing a shift in the output data. A value of 0 disables the self-test force.

SPI Bit

A value of 1 in the SPI bit sets the device to 3-wire SPI mode, and a value of 0 sets the device to 4-wire SPI mode.

INT_INVERT Bit

A value of 0 in the INT_INVERT bit sets the interrupts to active high, and a value of 1 sets the interrupts to active low.

FULL_RES Bit

When this bit is set to a value of 1, the device is in full resolution mode, where the output resolution increases with the *g* range set by the range bits to maintain a 4 m*g*/LSB scale factor. When the FULL_RES bit is set to 0, the device is in 10-bit mode, and the range bits determine the maximum *g* range and scale factor.

Justify Bit

A setting of 1 in the justify bit selects left (MSB) justified mode, and a setting of 0 selects right justified mode with sign extension.

Range Bits

These bits set the *g* range as described in Table 18.

Table 18. *g* Range Setting

Setting		
D1	**D0**	***g* Range**
0	0	±2 *g*
0	1	±4 *g*
1	0	±8 *g*
1	1	±16 *g*

Register 0x32 to Register 0x37—DATAX0, DATAX1, DATAY0, DATAY1, DATAZ0, DATAZ1 (Read Only)

These six bytes (Register 0x32 to Register 0x37) are eight bits each and hold the output data for each axis. Register 0x32 and Register 0x33 hold the output data for the x-axis, Register 0x34 and Register 0x35 hold the output data for the y-axis, and Register 0x36 and Register 0x37 hold the output data for the z-axis. The output data is twos complement, with DATAx0 as the least significant byte and DATAx1 as the most significant byte, where x represent X, Y, or Z. The DATA_FORMAT register (Address 0x31) controls the format of the data. It is recommended that a multiple-byte read of all registers be performed to prevent a change in data between reads of sequential registers.

Register 0x38—FIFO_CTL (Read/Write)

D7	D6	D5	D4	D3	D2	D1	D0
FIFO_MODE		Trigger	Samples				

FIFO_MODE Bits

These bits set the FIFO mode, as described in Table 19.

Table 19. FIFO Modes

Setting D7	Setting D6	Mode	Function
0	0	Bypass	FIFO is bypassed.
0	1	FIFO	FIFO collects up to 32 values and then stops collecting data, collecting new data only when FIFO is not full.
1	0	Stream	FIFO holds the last 32 data values. When FIFO is full, the oldest data is overwritten with newer data.
1	1	Trigger	When triggered by the trigger bit, FIFO holds the last data samples before the trigger event and then continues to collect data until full. New data is collected only when FIFO is not full.

Trigger Bit

A value of 0 in the trigger bit links the trigger event of trigger mode to INT1, and a value of 1 links the trigger event to INT2.

Samples Bits

The function of these bits depends on the FIFO mode selected (see Table 20). Entering a value of 0 in the samples bits immediately sets the watermark status bit in the INT_SOURCE register, regardless of which FIFO mode is selected. Undesirable operation may occur if a value of 0 is used for the samples bits when trigger mode is used.

Table 20. Samples Bits Functions

FIFO Mode	Samples Bits Function
Bypass	None.
FIFO	Specifies how many FIFO entries are needed to trigger a watermark interrupt.
Stream	Specifies how many FIFO entries are needed to trigger a watermark interrupt.
Trigger	Specifies how many FIFO samples are retained in the FIFO buffer before a trigger event.

0x39—FIFO_STATUS (Read Only)

D7	D6	D5	D4	D3	D2	D1	D0
FIFO_TRIG	0	Entries					

FIFO_TRIG Bit

A 1 in the FIFO_TRIG bit corresponds to a trigger event occurring, and a 0 means that a FIFO trigger event has not occurred.

Entries Bits

These bits report how many data values are stored in FIFO. Access to collect the data from FIFO is provided through the DATAX, DATAY, and DATAZ registers. FIFO reads must be done in burst or multiple-byte mode because each FIFO level is cleared after any read (single- or multiple-byte) of FIFO. FIFO stores a maximum of 32 entries, which equates to a maximum of 33 entries available at any given time because an additional entry is available at the output filter of the device.

APPLICATIONS INFORMATION

POWER SUPPLY DECOUPLING

A 1 μF tantalum capacitor (C_S) at V_S and a 0.1 μF ceramic capacitor (C_{IO}) at $V_{DD\ I/O}$ placed close to the ADXL345 supply pins is used for testing and is recommended to adequately decouple the accelerometer from noise on the power supply. If additional decoupling is necessary, a resistor or ferrite bead, no larger than 100 Ω, in series with V_S may be helpful. Additionally, increasing the bypass capacitance on V_S to a 10 μF tantalum capacitor in parallel with a 0.1 μF ceramic capacitor may also improve noise.

Care should be taken to ensure that the connection from the ADXL345 ground to the power supply ground has low impedance because noise transmitted through ground has an effect similar to noise transmitted through V_S. It is recommended that V_S and $V_{DD\ I/O}$ be separate supplies to minimize digital clocking noise on the V_S supply. If this is not possible, additional filtering of the supplies as previously mentioned may be necessary.

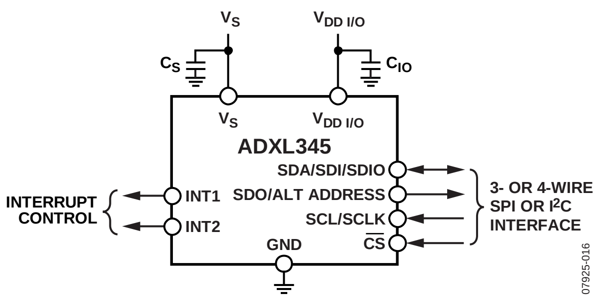

Figure 11. Application Diagram

MECHANICAL CONSIDERATIONS FOR MOUNTING

The ADXL345 should be mounted on the PCB in a location close to a hard mounting point of the PCB to the case. Mounting the ADXL345 at an unsupported PCB location, as shown in Figure 12, may result in large, apparent measurement errors due to undampened PCB vibration. Locating the accelerometer near a hard mounting point ensures that any PCB vibration at the accelerometer is above the accelerometer's mechanical sensor resonant frequency and, therefore, effectively invisible to the accelerometer.

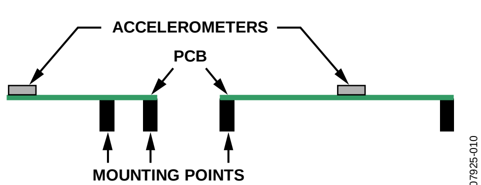

Figure 12. Incorrectly Placed Accelerometers

TAP DETECTION

The tap interrupt function is capable of detecting either single or double taps. The following parameters are shown in Figure 13 for a valid single and valid double tap event:

- The tap detection threshold is defined by the THRESH_TAP register (Address 0x1D).
- The maximum tap duration time is defined by the DUR register (Address 0x21).
- The tap latency time is defined by the latent register (Address 0x22) and is the waiting period from the end of the first tap until the start of the time window, when a second tap can be detected, which is determined by the value in the window register (Address 0x23).
- The interval after the latency time (set by the latent register) is defined by the window register. Although a second tap must begin after the latency time has expired, it need not finish before the end of the time defined by the window register.

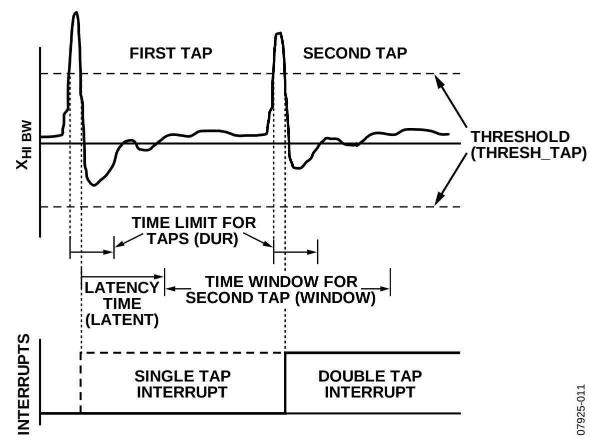

Figure 13. Tap Interrupt Function with Valid Single and Double Taps

If only the single tap function is in use, the single tap interrupt is triggered when the acceleration goes below the threshold, as long as DUR has not been exceeded. If both single and double tap functions are in use, the single tap interrupt is triggered when the double tap event has been either validated or invalidated.

Several events can occur to invalidate the second tap of a double tap event. First, if the suppress bit in the TAP_AXES register (Address 0x2A) is set, any acceleration spike above the threshold during the latency time (set by the latent register) invalidates the double tap detection, as shown in Figure 14.

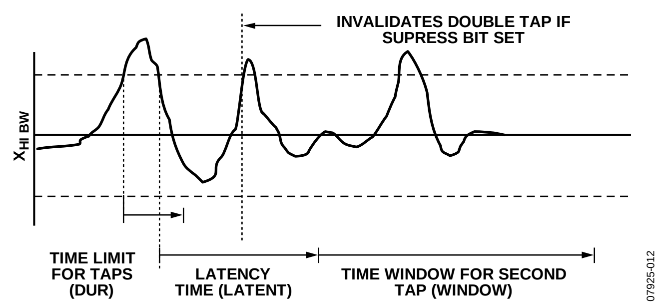

Figure 14. Double Tap Event Invalid Due to High g Event When the Suppress Bit Is Set

A double tap event can also be invalidated if acceleration above the threshold is detected at the start of the time window for the second tap (set by the window register). This results in an invalid double tap at the start of this window, as shown in Figure 15. Additionally, a double tap event can be invalidated if an acceleration exceeds the time limit for taps (set by the DUR register), resulting in an invalid double tap at the end of the DUR time limit for the second tap event, also shown in Figure 15.

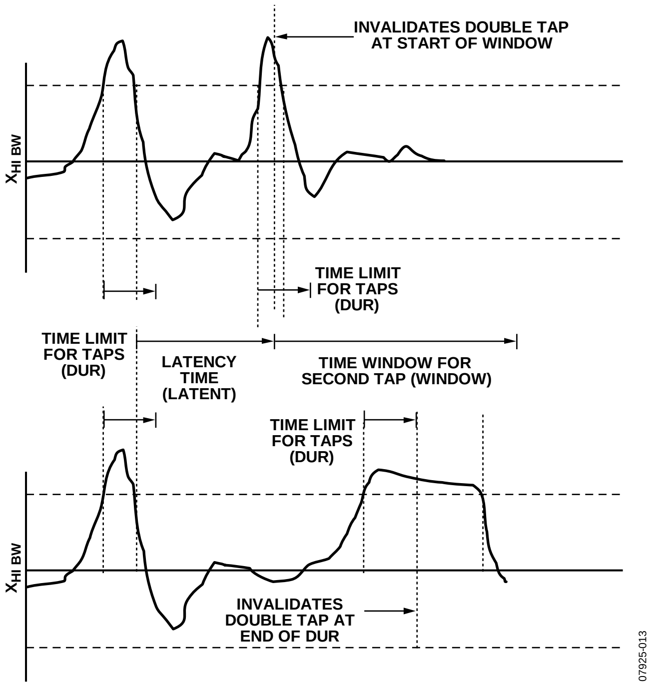

Figure 15. Tap Interrupt Function with Invalid Double Taps

Single taps, double taps, or both can be detected by setting the respective bits in the INT_ENABLE register (Address 0x2E). Control over participation of each of the three axes in single tap/double tap detection is exerted by setting the appropriate bits in the TAP_AXES register (Address 0x2A). For the double tap function to operate, both the latent and window registers must be set to a nonzero value.

Every mechanical system has somewhat different single tap/double tap responses based on the mechanical characteristics of the system. Therefore, some experimentation with values for the latent, window, and THRESH_TAP registers is required. In general, a good starting point is to set the latent register to a value greater than 0x10, to set the window register to a value greater than 0x10, and to set the THRESH_TAP register to be greater than 3 *g*. Setting a very low value in the latent, window, or THRESH_TAP register may result in an unpredictable response due to the accelerometer picking up echoes of the tap inputs.

After a tap interrupt has been received, the first axis to exceed the THRESH_TAP level is reported in the ACT_TAP_STATUS register (Address 0x2B). This register is never cleared, but is overwritten with new data.

THRESHOLD

The lower output data rates are achieved by decimating a common sampling frequency inside the device. The activity, free-fall, and single tap/double tap detection functions are performed using unfiltered data. Since the output data is filtered, the high frequency and high *g* data that is used to determine activity, free-fall, and single tap/double tap events may not be present if the output of the accelerometer is examined. This may result in trigger events being detected when acceleration does not appear to trigger an event because the unfiltered data may have exceeded a threshold or remained below a threshold for a certain period of time while the filtered output data has not exceeded such a threshold.

LINK MODE

The function of the link bit is to reduce the number of activity interrupts that the processor must service by setting the device to look for activity only after inactivity. For proper operation of this feature, the processor must still respond to the activity and inactivity interrupts by reading the INT_SOURCE register (Address 0x30) and, therefore, clearing the interrupts. If an activity interrupt is not cleared, the part cannot go into autosleep mode. The asleep bit in the ACT_TAP_STATUS register (Address 0x2B) indicates if the part is asleep.

SLEEP MODE VS. LOW POWER MODE

In applications where a low data rate is sufficient and low power consumption is desired, it is recommended that the low power mode be used in conjunction with the FIFO. The sleep mode, while offering a low data rate and low average current consumption, suppresses the DATA_READY interrupt, preventing the accelerometer from sending an interrupt signal to the host processor when data is ready to be collected. In this application, setting the part into low power mode (by setting the LOW_POWER bit in the BW_RATE register) and enabling the FIFO in FIFO mode to collect a large value of samples reduces the power consumption of the ADXL345 and allows the host processor to go to sleep while the FIFO is filling up.

USING SELF-TEST

The self-test change is defined as the difference between the acceleration output of an axis with self-test enabled and the acceleration output of the same axis with self-test disabled (see Endnote 4 of Table 1). This definition assumes that the sensor does not move between these two measurements, because if the sensor moves, a non–self-test related shift corrupts the test.

Proper configuration of the ADXL345 is also necessary for an accurate self-test measurement. The part should be set with a data rate greater than or equal to 100 Hz. This is done by ensuring that a value greater than or equal to 0x0A is written into the rate bits (Bit D3 through Bit D0) in the BW_RATE register (Address 0x2C). It is also recommended that the part be set to full-resolution, 16 *g* mode to ensure that there is sufficient dynamic range for the entire self-test shift. This is done by setting Bit D3 of the DATA_FORMAT register (Address 0x31) and writing a value of 0x03 to the range bits (Bit D1 and Bit D0) of the DATA_FORMAT register (Address 0x31). This results in a high dynamic range for measurement and a 3.9 m*g*/LSB scale factor.

After the part is configured for accurate self-test measurement, several samples of x-, y-, and z-axis acceleration data should be retrieved from the sensor and averaged together. The number of samples averaged is a choice of the system designer, but a recommended starting point is 0.1 sec worth of data, which corresponds to 10 samples at 100 Hz data rate. The averaged values should be stored and labeled appropriately as the self-test disabled data, that is, X_{ST_OFF}, Y_{ST_OFF}, and Z_{ST_OFF}.

Next, self-test should be enabled by setting Bit D7 of the DATA_FORMAT register (Address 0x31). The output needs some time (about four samples) to settle after enabling self-test. After allowing the output to settle, several samples of the x-, y-, and z-axis acceleration data should be taken again and averaged. It is recommended that the same number of samples be taken for this average as was previously taken. These averaged values should again be stored and labeled appropriately as the value with self-test enabled, that is, X_{ST_ON}, Y_{ST_ON}, and Z_{ST_ON}. Self-test can then be disabled by clearing Bit D7 of the DATA_FORMAT register (Address 0x31).

With the stored values for self-test enabled and disabled, the self-test change is as follows:

$$X_{ST} = X_{ST\_ON} - X_{ST\_OFF}$$

$$Y_{ST} = Y_{ST\_ON} - Y_{ST\_OFF}$$

$$Z_{ST} = Z_{ST\_ON} - Z_{ST\_OFF}$$

Because the measured output for each axis is expressed in LSBs, X_{ST}, Y_{ST}, and Z_{ST} are also expressed in LSBs. These values can be converted to *g*'s of acceleration by multiplying each value by the 3.9 m*g*/LSB scale factor, if configured for full-resolution, 16 *g* mode. Additionally, Table 12 through Table 15 correspond to the self-test range converted to LSBs and can be compared with the measured self-test change. If the part was placed into full-resolution, 16 *g* mode, the values listed in Table 12 should be used. Although the fixed 10-bit mode or a range other than 16 *g* can be used, a different set of values, as indicated in Table 13 through Table 15, would need to be used. Using a range below 8 *g* may result in insufficient dynamic range and should be considered when selecting the range of operation for measuring self-test. In addition, note that the range in Table 1 and the values in Table 12 through Table 15 take into account all possible supply voltages, V_S, and no additional conversion due to V_S is necessary.

If the self-test change is within the valid range, the test is considered successful. Generally, a part is considered to pass if the minimum magnitude of change is achieved. However, a part that changes by more than the maximum magnitude is not necessarily a failure.

AXES OF ACCELERATION SENSITIVITY

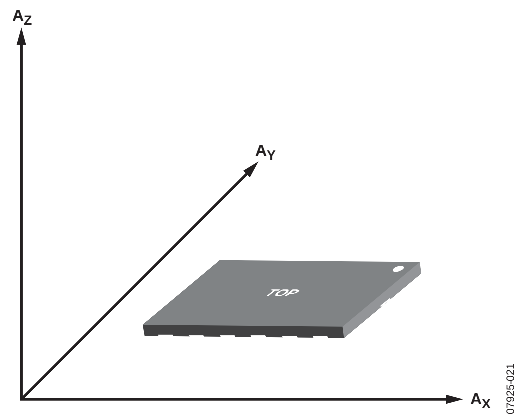

Figure 16. Axes of Acceleration Sensitivity (Corresponding Output Voltage Increases When Accelerated Along the Sensitive Axis)

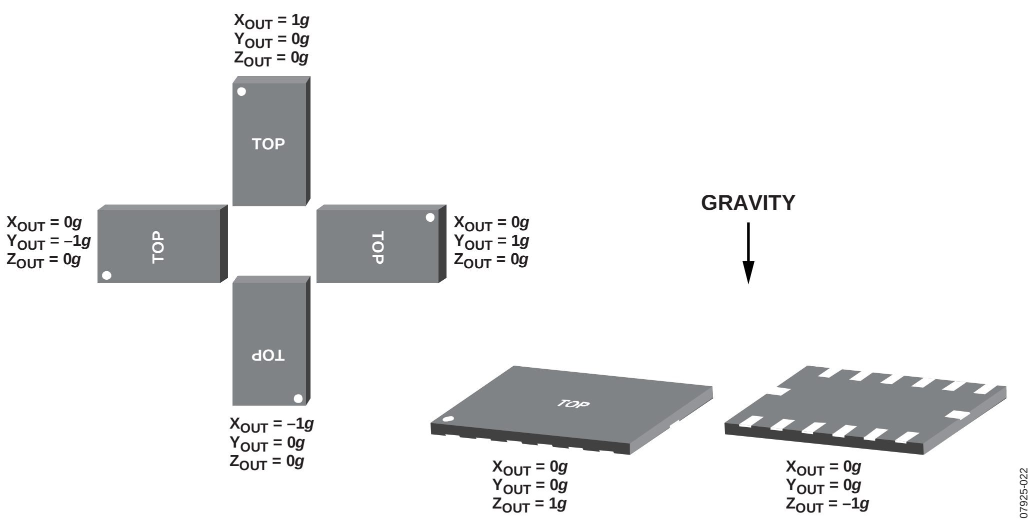

Figure 17. Output Response vs. Orientation to Gravity

LAYOUT AND DESIGN RECOMMENDATIONS

Figure 18 shows the recommended printed wiring board land pattern. Figure 19 and Table 21 provide details about the recommended soldering profile.

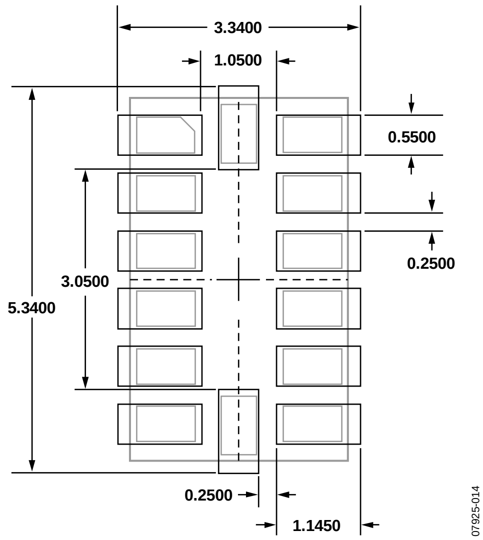

Figure 18. Recommended Printed Wiring Board Land Pattern (Dimensions shown in millimeters)

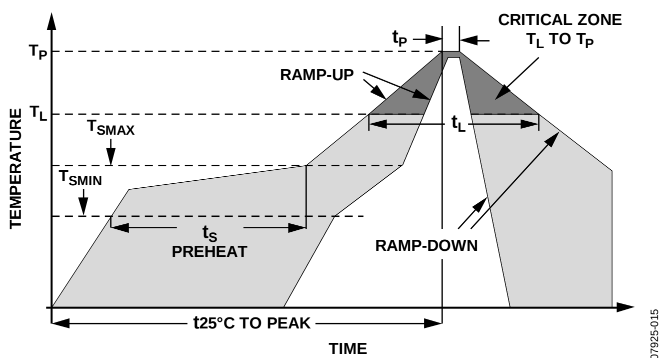

Figure 19. Recommended Soldering Profile

Table 21. Recommended Soldering Profile[1, 2]

Profile Feature	Condition	
	Sn63/Pb37	**Pb-Free**
Average Ramp Rate from Liquid Temperature (T_L) to Peak Temperature (T_P)	3°C/sec max	3°C/sec max
Preheat		
Minimum Temperature (T_{SMIN})	100°C	150°C
Maximum Temperature (T_{SMAX})	150°C	200°C
Time from T_{SMIN} to T_{SMAX} (t_S)	60 sec to 120 sec	60 sec to 180 sec
T_{SMAX} to T_L Ramp-Up Rate	3°C/sec max	3°C/sec max
Liquid Temperature (T_L)	183°C	217°C
Time Maintained Above T_L (t_L)	60 sec to 150 sec	60 sec to 150 sec
Peak Temperature (T_P)	240 + 0/−5°C	260 + 0/−5°C
Time of Actual T_P − 5°C (t_P)	10 sec to 30 sec	20 sec to 40 sec
Ramp-Down Rate	6°C/sec max	6°C/sec max
Time 25°C to Peak Temperature	6 minutes max	8 minutes max

[1] Based on JEDEC Standard J-STD-020D.1.
[2] For best results, the soldering profile should be in accordance with the recommendations of the manufacturer of the solder paste used.

OUTLINE DIMENSIONS

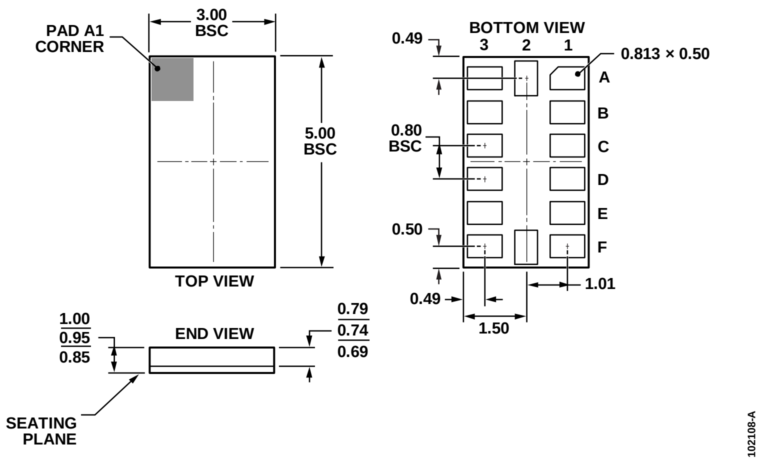

Figure 20. 14-Terminal Land Grid Array [LGA]
(CC-14-1)
Solder Terminations Finish Is Au over Ni
(Dimensions shown in millimeters)

ORDERING GUIDE

Model	Measurement Range (*g*)	Specified Voltage (V)	Temperature Range	Package Description	Package Option
ADXL345BCCZ[1]	±2, ±4, ±8, ±16	2.5	−40°C to +85°C	14-Terminal Land Grid Array [LGA]	CC-14-1
ADXL345BCCZ-RL[1]	±2, ±4, ±8, ±16	2.5	−40°C to +85°C	14-Terminal Land Grid Array [LGA]	CC-14-1
ADXL345BCCZ-RL7[1]	±2, ±4, ±8, ±16	2.5	−40°C to +85°C	14- Terminal Land Grid Array [LGA]	CC-14-1
EVAL-ADXL345Z[1]				Evaluation Board	
EVAL-ADXL345Z-M[1]				Analog Devices Inertial Sensor Evaluation System, Includes ADXL345 Satellite	
EVAL-ADXL345Z-S[1]				ADXL345 Satellite, Standalone	

[1] Z = RoHS Compliant Part.

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ADXL345 Quick Start Guide

by Tomoaki Tusuzki

PHYSICAL MOUNTING

The ADXL345 is 3-axis accelerometer. The sensing axes are shown in Figure 1.

The ADXL345 senses positive acceleration when it is accelerated in the positive direction of the sensing axes. The user must be careful when sensing gravity because positive acceleration is sensed when the direction of the sensing axis is opposite to gravity. Figure 2 shows the output response to gravity.

The ADXL345 is supplied in a small, thin, 3 mm × 5 mm × 1 mm, 14-lead, plastic package. Refer to the ADXL345 data sheet for recommended printed circuit board land pattern.

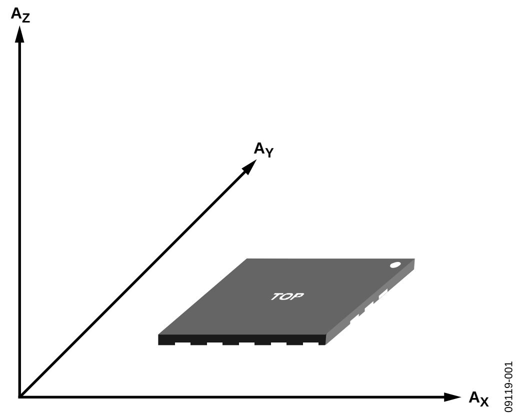

Figure 1. Sensing Axes of ADXL345

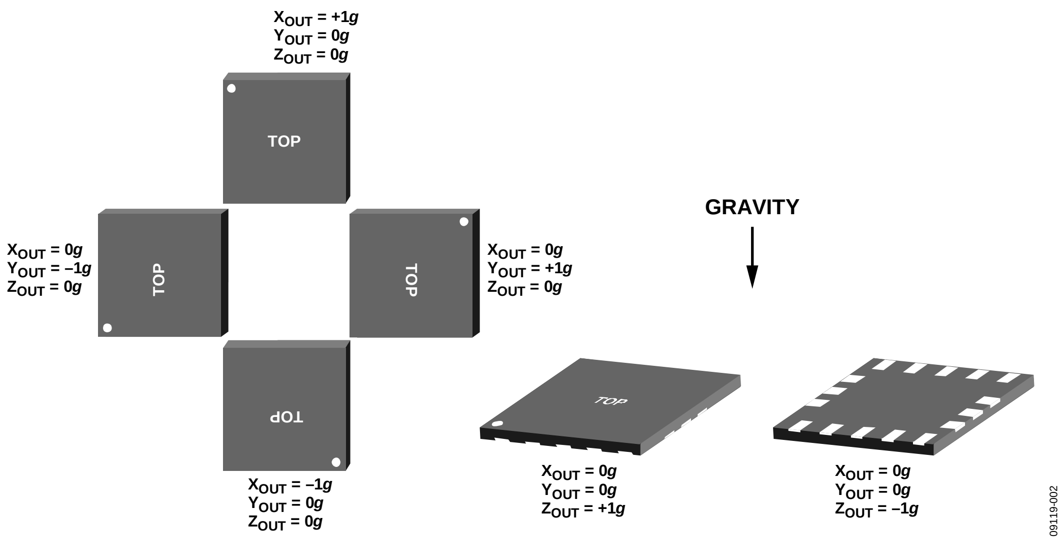

Figure 2. Output Response vs. Orientation to Gravity

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ELECTRICAL CONNECTION

ADXL345 communication is done via either I²C or SPI (3- or 4-wire mode). Figure 3 shows the recommended electrical connections for 4-wire SPI mode. Note that the SDO pin can be disconnected when using 3-wire SPI mode.

Figure 4 shows the recommended electrical connection for I²C mode. The 7-bit I²C address for the device is 0x53, followed by the R/$\overline{W}$ bit. The user can select an alternate I²C address by connecting the SDO/ALT ADDRESS pin to the $V_{DD\ I/O}$ pin. The 7-bit I²C address for that configuration is 0x1D, followed by the R/$\overline{W}$ bit.

Refer to the ADXL345 data sheet for details on power supply decoupling.

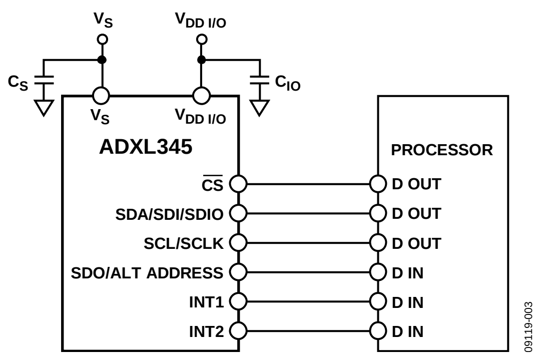


Figure 3. Recommended Connection for 4-Wire SPI Mode

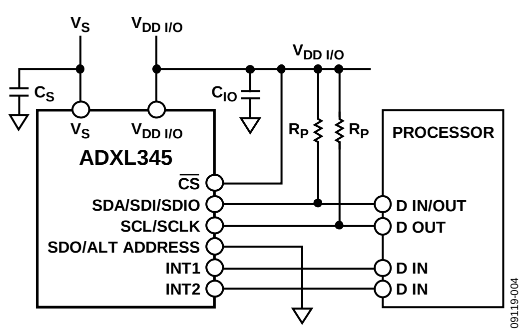


Figure 4. Recommended Connection for I²C Mode

COMMUNICATION INTERFACE

Table 1 gives the list of typical configuration settings for the master processor requirements for SPI communication with the ADXL345. These settings are normally in control registers. Refer to the ADXL345 data sheet for timing specification and a command sequence.

Table 1. SPI Settings

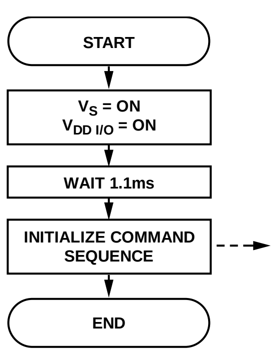
Processor Setting	Description
Master	ADXL345 operates as slave
SPI Mode	Clock polarity (CPOL) = 1 Clock phase (CPHA) = 1
Bit Sequence	MSB first mode

For I²C communication, refer to the ADXL345 data sheet and *UM10204 I²C-Bus Specification and User Manual*, Rev. 03—19 June 2007 for processor settings as well as timing specifications and a command sequence.

Sometimes it is important to confirm the validity of a communication sequence before going to the next design stage. This can be done by reading the DEVID register (Address 0x00). It is a read only register that contains 0xE5. If the data read from DEVID is not 0xE5, it is the indication that either the physical connection or command sequence is incorrect.

INITIALIZATION

Figure 5 shows the minimum initialization sequence. The ADXL345 operates in a 100 Hz ODR with a DATA_READY interrupt on the INT1 pin during this start-up sequence. When setting other interrupts or using the FIFO, it is recommended that those registers used are set before the POWER_CTL and INT_ENABLE registers. Refer to the ADXL345 data sheet and the AN-1025 application note for other operation modes of ADXL345 and details about FIFO.



STEP	REGISTER ADDRESS	REGISTER NAME	DATA	DESCRIPTION
1	0x31	DATA_FORMAT	0x0B	±16*g*, 13-BIT MODE
2	0x2D	POWER_CTL	0x08	START MEASUREMENT
3	0x2E	INT_ENABLE	0x80	ENABLE DATA_READY INTERRUPT.

09119-005

Figure 5. Minimum Initialization Sequence

READING OUTPUT DATA

The DATA_READY interrupt signal indicates that 3-axis of acceleration data is updated in the data registers. It is latched high when new data is ready. (The interrupt can be configured to be latched from low-to-high through the DATA_FORMAT register. Refer to the ADXL345 data sheet for details.) Use the low-to-high transition to trigger action on an interrupt service routine. Data is read from the DATAX0, DATAX1, DATAY0, DATAY1, DATAZ0, and DATAZ1 registers. To ensure data coherency, it is recommended that multibyte reads are used to retrieve data from the ADXL345. Figure 7 shows the read sequence example for 4-wire SPI.

DATA FORMAT

The data format of the ADXL345 is 16 bits. Once acceleration data is acquired from data registers, the user must reconstruct the data. DATAX0 is the low byte register for X-axis acceleration and DATAX1 is the high byte register. In 13-bit mode, the upper 4 bits are sign bits (see Figure 6). Note that other data formats are available by setting the DATA_FORMAT register. See the ADXL345 data sheet for more details.

The ADXL345 uses twos complement data format. When in 13-bit mode, 1 LSB represents about 3.9 m*g*.

Table 2. ADXL345 Output Data Format

16-Bit Code (Hex)	Twos Complement Representation (Dec)	Acceleration (m*g*)
0FFF	4095	+1599
…	…	…
0002	+2	+7.8
0001	+1	+3.9
0000	0	0
FFFF	−1	−3.9
FFFE	−2	−7.8
…	…	…
F000	−4095	−1600

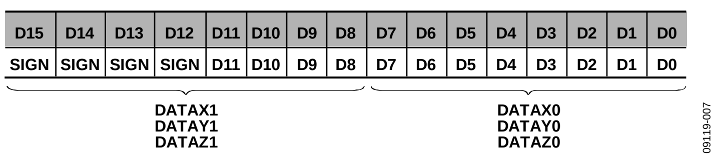


Figure 6. Data Construction

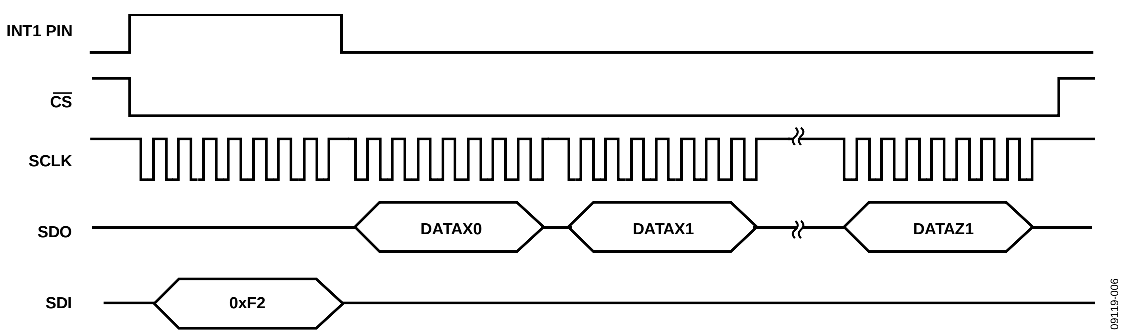
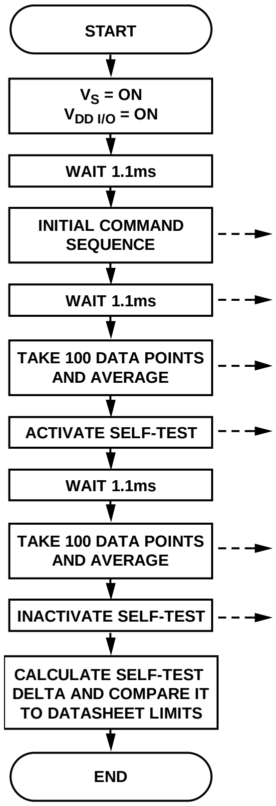


Figure 7. Data Read Timing Sequence for 4-Wire SPI Connection

USING THE SELF-TEST FEATURE

The ADXL345 provides a self-test feature that enables an electromechanical test on the device without external mechanical stimulus. Figure 8 outlines a recommended self-test sequence. Note that the ADXL345 should be placed in a stable environment when conducting the self-test sequence.



STEP	REGISTER ADDRESS	REGISTER NAME	DATA	DESCRIPTION
1	0x31	DATA_FORMAT	0x0B	±16*g*, 13-BIT MODE
2	0x2D	POWER_CTL	0x08	START MEASUREMENT
3	0x2E	INT_ENABLE	0x80	ENABLE DATA_READY INTERRUPT

WHEN AT ODR = 100Hz (WAIT TIME DEPENDS ON ODR SETTLING AND 1.1ms + 1/ODR)

IT IS TO MINIMIZE THE EFFECT OF NOISE

STEP	REGISTER ADDRESS	REGISTER NAME	DATA	DESCRIPTION
1	0x31	DATA_FORMAT	0x8B	SELF-TEST ON, ±16*g*, 13-BIT MODE

IT IS TO MINIMIZE THE EFFECT OF NOISE

STEP	REGISTER ADDRESS	REGISTER NAME	DATA	DESCRIPTION
1	0x31	DATA_FORMAT	0x0B	SELF-TEST OFF, ±16*g*, 13-BIT MODE

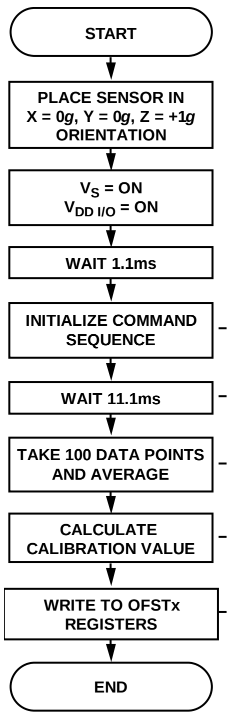
09119-008

Figure 8. Self-Test Sequence

USING OFFSET REGISTERS

The ADXL345 has offset registers that facilitate offset calibration. The data format for the offset registers is 8-bit, twos compliment. The resolution of the offset registers is about 15.6 m*g*/LSB. If offset calibration must be finer than 15.6 m*g*/LSB, the calibration needs to be done at the processor. The offset register adds the value written in the register to measured acceleration. For example, if the offset is +156 m*g*, then −156 m*g* should be written to offset register. Figure 9 shows the typical offset calibration sequence.

For this routine, X/Y axes errors are zero when 0 *g* input is applied, whereas Z-axis errors are zero when 1 *g* input is applied. Greater accuracy can be achieved if it is possible to rotate the ADXL345 at calibration.



STEP	REGISTER ADDRESS	REGISTER NAME	DATA	DESCRIPTION
1	0x31	DATA_FORMAT	0x0B	±16*g*, 13-BIT MODE
2	0x2D	POWER_CTL	0x08	START MEASUREMENT
3	0x2E	INT_ENABLE	0x80	ENABLE DATA_READY INTERRUPT

WHEN AT ODR = 100Hz (WAIT TIME DEPENDS ON ODR SETTLING AND 1.1ms + 1/ODR)

IT IS TO MINIMIZE THE EFFECT OF NOISE

X_CALIB = –(OUTPUT (X) ÷ 4)
Y_CALIB = –(OUTPUT (Y) ÷ 4)
Z_CALIB = –((OUTPUT (Z) – 256) ÷ 4)

STEP	REGISTER ADDRESS	REGISTER NAME	DATA	DESCRIPTION
1	0x1E	OFSTX	X_CALIB	X_CALIB TO BE 8 BIT
2	0x1F	OFSTY	Y_CALIB	Y_CALIB TO BE 8 BIT
3	0x20	OFSTZ	Z_CALIB	Z_CALIB TO BE 8 BIT

09119-009

Figure 9. Offset Calibration Sequence

NOTES

NOTES

October 2005

BSS138

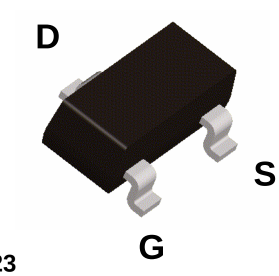
N-Channel Logic Level Enhancement Mode Field Effect Transistor

General Description

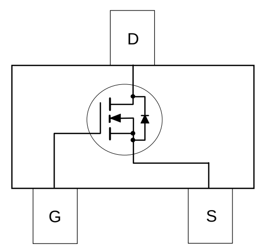
These N-Channel enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance.These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

Features

- 0.22 A, 50 V. $R_{DS(ON)}$ = 3.5Ω @ V_{GS} = 10 V
  $R_{DS(ON)}$ = 6.0Ω @ V_{GS} = 4.5 V
- High density cell design for extremely low $R_{DS(ON)}$
- Rugged and Reliable
- Compact industry standard SOT-23 surface mount package



SOT-23



Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain-Source Voltage	50	V
V_{GSS}	Gate-Source Voltage	±20	V
I_D	Drain Current – Continuous (Note 1)	0.22	A
	– Pulsed	0.88	
P_D	Maximum Power Dissipation (Note 1)	0.36	W
	Derate Above 25°C	2.8	mW/°C
T_J, T_{STG}	Operating and Storage Junction Temperature Range	–55 to +150	°C
T_L	Maximum Lead Temperature for Soldering Purposes, 1/16" from Case for 10 Seconds	300	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1)	350	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
SS	BSS138	7''	8mm	3000 units

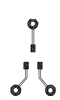
Electrical Characteristics

$T_A = 25°C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain–Source Breakdown Voltage	$V_{GS} = 0$ V, $I_D = 250$ µA	50			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250$ µA, Referenced to 25°C		72		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 50$ V, $V_{GS} = 0$ V			0.5	µA
		$V_{DS} = 50$ V, $V_{GS} = 0$ V $T_J = 125°C$			5	µA
		$V_{DS} = 30$ V, $V_{GS} = 0$ V			100	nA
I_{GSS}	Gate–Body Leakage.	$V_{GS} = \pm20$ V, $V_{DS} = 0$ V			±100	nA
On Characteristics (Note 2)						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 1$ mA	0.8	1.3	1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = 1$ mA, Referenced to 25°C		–2		mV/°C
$R_{DS(on)}$	Static Drain–Source On–Resistance	$V_{GS} = 10$ V, $I_D = 0.22$ A $V_{GS} = 4.5$ V, $I_D = 0.22$ A $V_{GS} = 10$ V, $I_D = 0.22$ A, $T_J = 125°C$		0.7 1.0 1.1	3.5 6.0 5.8	Ω
$I_{D(on)}$	On–State Drain Current	$V_{GS} = 10$ V, $V_{DS} = 5$ V	0.2			A
g_{FS}	Forward Transconductance	$V_{DS} = 10$V, $I_D = 0.22$ A	0.12	0.5		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = 25$ V, $V_{GS} = 0$ V, f = 1.0 MHz		27		pF
C_{oss}	Output Capacitance			13		pF
C_{rss}	Reverse Transfer Capacitance			6		pF
R_G	Gate Resistance	$V_{GS} = 15$ mV, f = 1.0 MHz		9		Ω
Switching Characteristics (Note 2)						
$t_{d(on)}$	Turn–On Delay Time	$V_{DD} = 30$ V, $I_D = 0.29$ A, $V_{GS} = 10$ V, $R_{GEN} = 6$ Ω		2.5	5	ns
t_r	Turn–On Rise Time			9	18	ns
$t_{d(off)}$	Turn–Off Delay Time			20	36	ns
t_f	Turn–Off Fall Time			7	14	ns
Q_g	Total Gate Charge	$V_{DS} = 25$ V, $I_D = 0.22$ A, $V_{GS} = 10$ V		1.7	2.4	nC
Q_{gs}	Gate–Source Charge			0.1		nC
Q_{gd}	Gate–Drain Charge			0.4		nC
Drain–Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain–Source Diode Forward Current				0.22	A
V_{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0$ V, $I_S = 0.44$ A (Note 2)		0.8	1.4	V

Notes:

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 350°C/W when mounted on a minimum pad..

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width ≤ 300 µs, Duty Cycle ≤ 2.0%

Typical Characteristics

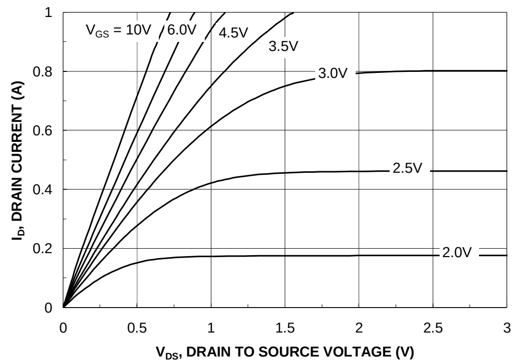


Figure 1. On-Region Characteristics.

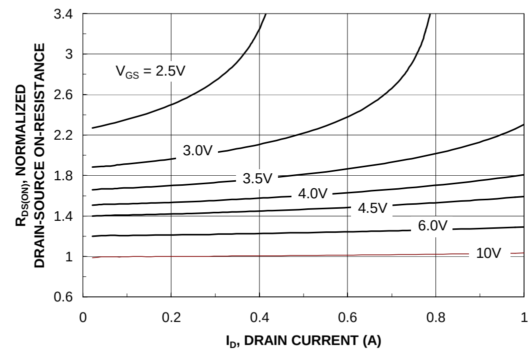


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

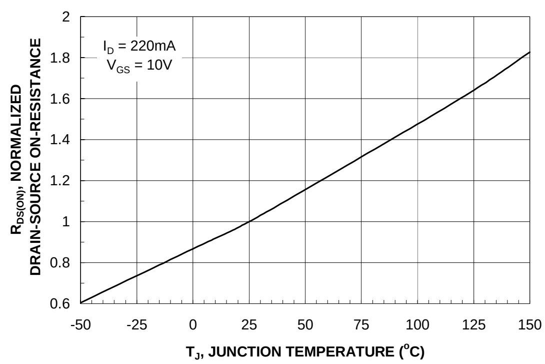


Figure 3. On-Resistance Variation with Temperature.

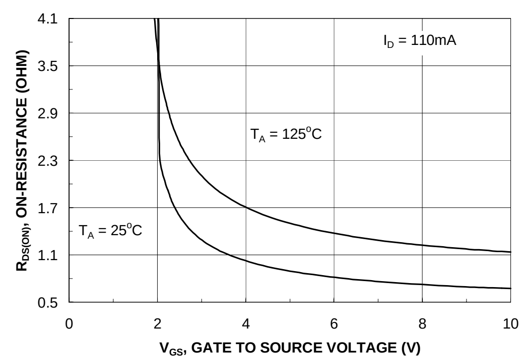


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

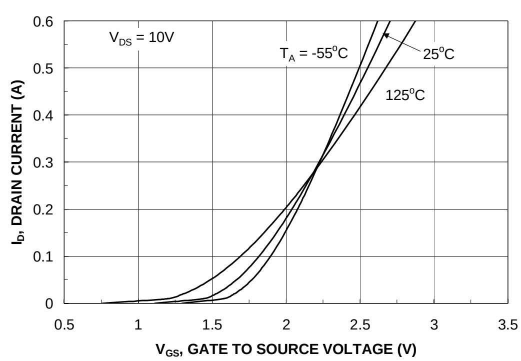


Figure 5. Transfer Characteristics.

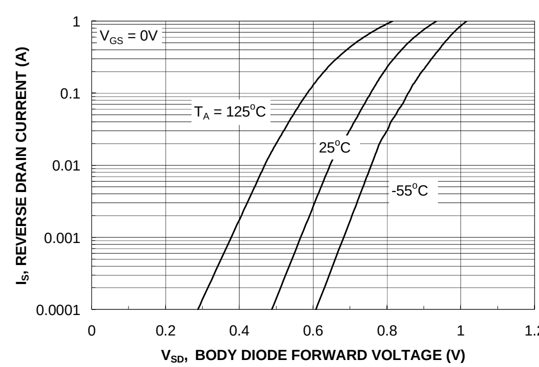


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics

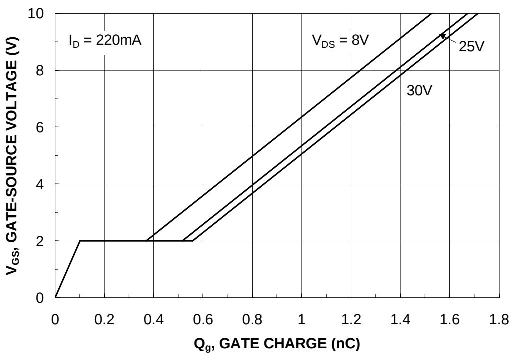


Figure 7. Gate Charge Characteristics.

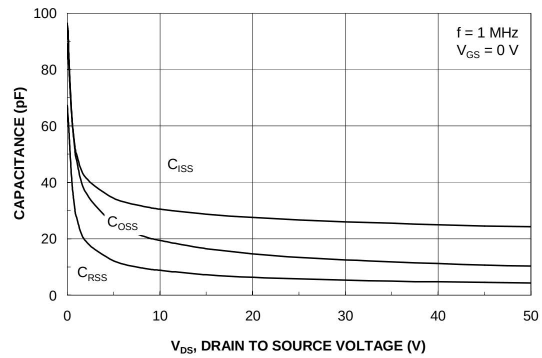


Figure 8. Capacitance Characteristics.

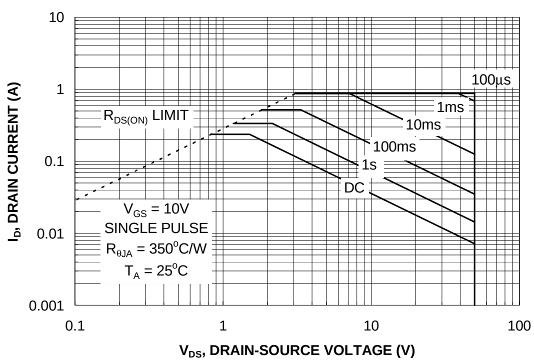


Figure 9. Maximum Safe Operating Area.

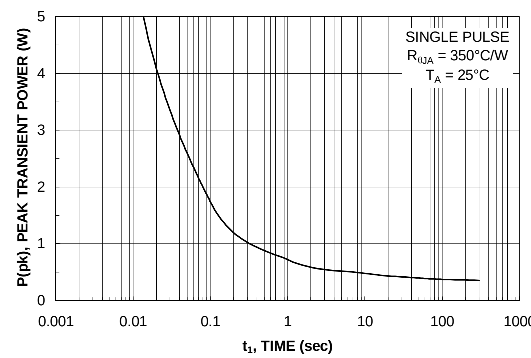


Figure 10. Single Pulse Maximum Power Dissipation.

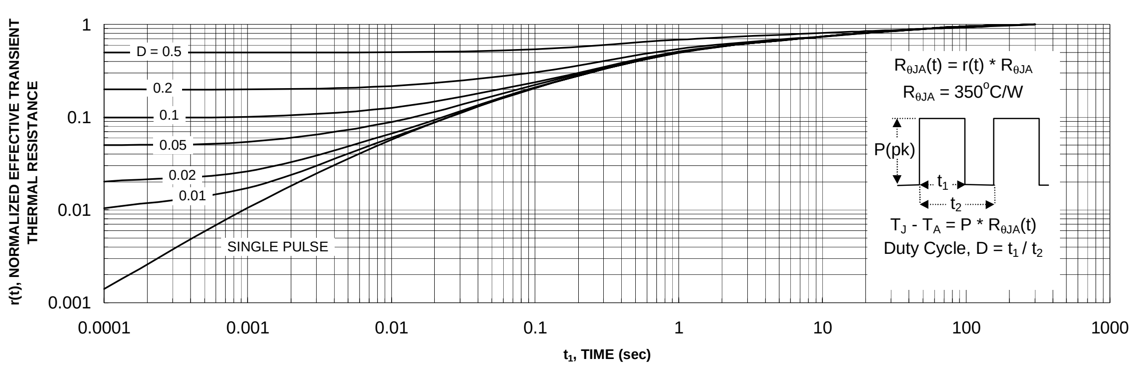


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1a.
Transient thermal response will change depending on the circuit board design.

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User's Guide

GDM12864HLCM

(Liquid Crystal Display Module)

For product support, contact

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CONTENTS

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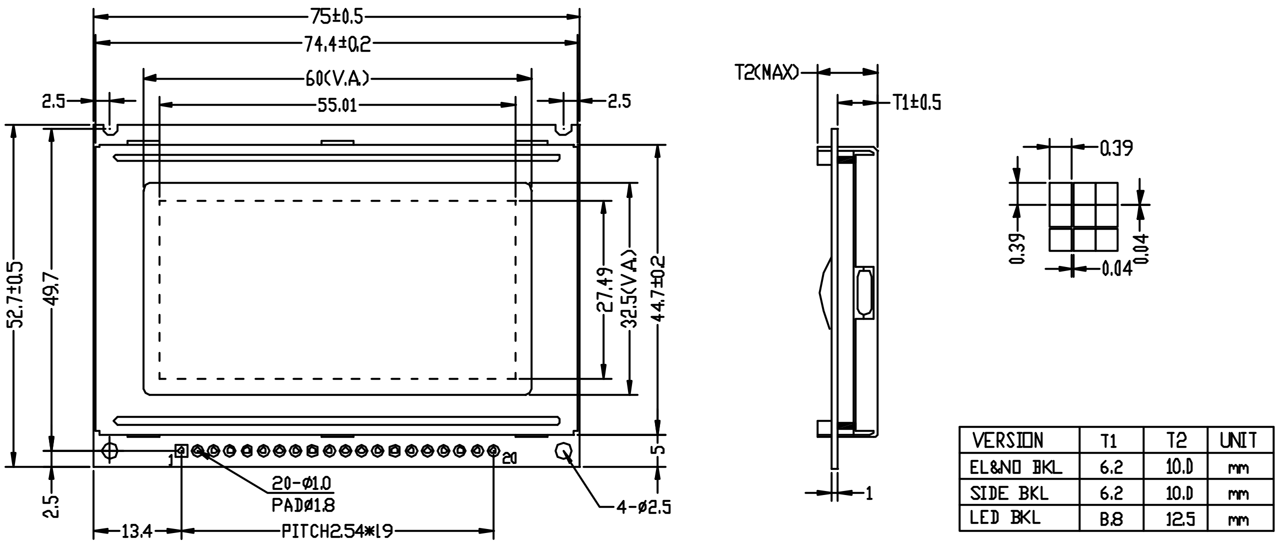
➢ Mechanical diagram



➢ Absolute maximum ratings

Item	Symbol	Min.	Max.	Unit
Supply voltage for logic	Vdd - Vss	0	6.5	V
Input voltage	Vin	0	Vdd	
Operating temperature range	T0p	-20	70	℃
Storage temperature range	Tst	-25	75	

➢ Interface pin connections

Pin No.	Symbol	Level	Description
1	Vdd	5.0V	Supply voltage for logic and LCD (+)
2	Vss	0V	Ground
3	V0	-	Operating voltage for LCD (variable)
4~11	DB0~DB7	H/L	Data bit 0~7
12	CS2	L	Chip select signal for IC2
13	CS1	L	Chip select signal for IC1
14	/RES	L	Reset signal
15	R/W	H/L	H: read (MUP<－module),L: write (MPU－>module)
16	D/I	H/L	H: data, L: instruction code
17	E	H, H L	Chip enable signal
18	VEE	-	Operating voltage for LCD (variable)
19	A	4.2V	Backlight power supply
20	K	0V	Backlight power supply

➢ Optical characteristics

STN Type display module (Ta=25℃, Vdd=5.0V)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Viewing angle	θ	Cr⩾2	-60	-	35	deg
	ϕ		-40	-	40	
Contrast ratio (rise)	Cr		-	6	-	
Response time (fall)	Tr	-	-	150	250	ms
	Tr	-	-	150	250	ms

➢ Electrical characteristics

Item		Symbol	Condition	Standard value			Unit
				Min.	Typ.	Max.	
Supply voltage for	Logic	Vdd - Vss	-	4.75	5.0	5.25	V
	LCD	Vdd-V0	-	-	9.5	-	
Supply current for	Logic	Idd	-	-	2.5	-	mA
	LCD	Iee	-	-	1.0	-	
Operating voltage for LCD (Recommended)		Vdd-v0	-	-	-	-	V
			25℃	-	9.5	-	
			-	-	-	-	
Input voltage	H: level	Vih	High level	0.7Vdd	-	Vdd	
	L: Level	Vil	Low level	0	-	0.3Vdd	

Electrical Absolute Maximum Ratings (KS0107B)

Parameter	Symbol	Rating	Unit	Note
Operating voltage	V_{DD}	-0.3 ~ +7.0	V	*1
Supply voltage	V_{EE}	V_{DD}-19.0 ~ V_{DD}+0.3	V	*4
Driver supply voltage	V_B	-0.3 ~ V_{DD}+0.3	V	*1,2
	V_{LCD}	V_{EE}-0.3 ~ V_{DD}+0.3	V	*3,4

***Notes:**

*1. Based on V_{SS} = 0V

*2. Applies to input terminals and I/O terminals at high impedance. (Except V0L, V1L, V4L, and V5L)

*3. Applies to V0L, V1L, V4L, and V5L.

*4. Voltage level: $V_{DD} \geqq V0 \geqq V1 \geqq V2 \geqq V3 \geqq V4 \geqq V5 \geqq V_{EE}$

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DC Electrical Characteristics (KS0107B)

(VDD= 4.5 to 5.5V, VSS=0V,VDD-VEE=8~17V,Ta= -30 to +85℃)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Note
Operating voltage	V_{DD}	-	4.5	-	5.5	V	
Input voltage	V_{IH}	-	$0.7V_{DD}$	-	V_{DD}		*1
	V_{IL}	-	V_{SS}	-	$0.3V_{DD}$		
output voltage	V_{OH}	I_{OH}= -0.4mA	V_{DD}-0.4	-	-		*2
	V_{OL}	I_{OL}= 0.4mA	-	-	0.4		
Input leakage current	I_{LKG}	$V_{IN}= V_{DD} \sim V_{SS}$	-1.0	-	+1.0	μA	*1
OSC Frequency	fosc	Rf=47kΩ±2% Cf=20pF±5%	315	450	585	kHz	
On Resistance (Vdiv-Ci)	R_{ONS}	V_{DD}-V_{EE}=17V Load current±150μA	-	-	1.5	kΩ	
Operating current	I_{DD1}	Master mode 1/128 Duty	-	-	1.0	mA	*3
	I_{DD2}	Master mode 1/128 Duty	-	-	0.2		*4
Supply Current	I_{EE}	Master mode 1/128 Duty	-	-	0.1		*5
Operating	f_{op1}	Master mode External Duty	50	-	600	kHz	
Frequency	f_{op2}	Slave mode	0.5	-	1500		

Notes

*1. Applies to input terminals FS, DS1, DS2, CR, SHL, MS and PCLK2 and I/O terminals DIO1, DIO2, M, and CL2 in the input state.

*2. Applies to output terminals CLK1, CLK2 and FRM and I/O terminals DIO1, DIO2, M, and CL2 in the output state.

*3. This value is specified about current flowing through V_{SS}.

Internal oscillation circuit: Rf=47kΩ, cf=20pF

Each terminals of DS1, DS2, FS, SHL, and MS is connected to V_{DD} and out is no load.

*4. This value is specified about current flowing through V_{SS}.

Each terminals is DS1, DS2, FS, SHL, PCLK2 and CR is connected to V_{DD},MS is connected to V_{SS} and CL2, M, DIO1 is external clock.

*5. This value is specified about current flowing through V_{EE}, Don’ t connect to V_{LCD}(V1~V5).

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Electrical Absolute Maximum Ratings (KS0108B)

Parameter	Symbol	Rating	Unit	Note
Operating voltage	V_{DD}	-0.3 ~ +7.0	V	*1
Supply voltage	V_{EE}	V_{DD}-19.0 ~ V_{DD}+0.3	V	*4
Driver supply voltage	V_B	-0.3 ~ V_{DD}+0.3	V	*1,3
	V_{LCD}	V_{EE}-0.3 ~ V_{DD}+0.3	V	*2

***Notes:**

*1. Based on V_{SS} = 0V

*2. Applies the same supply voltage to VEE. VLCD=VDD-VEE.

*3. Applies to M, FRM, CLK1, CLK2, CL, RESETB, ADC, CS1B, CS2B, CS3, E, R/W, RS and DB0~DB7.

*4. Applies V0L, V2L, V3L and V5L.

Voltage level: V_{DD}≥V0≥V1≥V2≥V3≥V4≥V5≥V_{EE}

DC Electrical Characteristics (KS0108B)

(VDD= 4.5 to 5.5V, VSS=0V,VDD-VEE=8~17V,Ta= -30 to +85℃)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Note
Operating voltage	V_{DD}	-	4.5	-	5.5	V	
Input High voltage	V_{IH1}	-	0.7$_{VDD}$	-	V_{DD}		*1
	V_{IH2}	-	2.0	-	V_{DD}		*2
Input Low voltage	V_{IL1}	-	0	-	0.3V_{DD}		*1
	V_{IL2}	-	0	-	0.8		*2
Output High Voltage	V_{OH}	I_{OH}= -0.2mA	2.4	-	-		*3
Output Low Voltage	V_{OL}	I_{OL}= 1.6mA	-	-	0.4		*3
Input leakage current	I_{LKG}	V_{IN}= V_{SS} ~ V_{DD}	-1.0	-	+1.0	µA	*4
Three-state (OFF) Input Current	ITSL	V_{IN}= V_{SS} ~ V_{DD}	-5.0	-	5.0		*5
Driver Input leakage current	IDIL	V_{IN}= V_{EE} ~ V_{DD}	-2.0		2.0		*6
On Resistance (Vdiv-Ci)	R_{ONS}	V_{DD}-V_{EE}=15V Load current±100µA	-	-	7.5	kΩ	*8
Operating current	I_{DD1}	During Display	-	-	0.1	mA	*7
	I_{DD2}	During Access Access Cycle=1MHz	-	-	0.5		*7

Notes

*1. CL, FRM, M, RSTB, CLK1, CLK2

*2. CS1B, CS2B, CS3, E, R/W, RS, DB0~DB7

*3. DB0~DB7

*4. Except DB0~DB7

*5. DB0~DB7 at high impedance

*6. V0, V1, V3, V3, V4, V5

*7. 1/64 duty, FCLK=250KHZ, Frame Frequency=70HKZ, Output: No Load

*8. VDD-VEE=15.5V
V0L>V2L>= VDD-2/7(VDD-VEE)>V3L= VEE+2/7(VDD-VEE)>V5L

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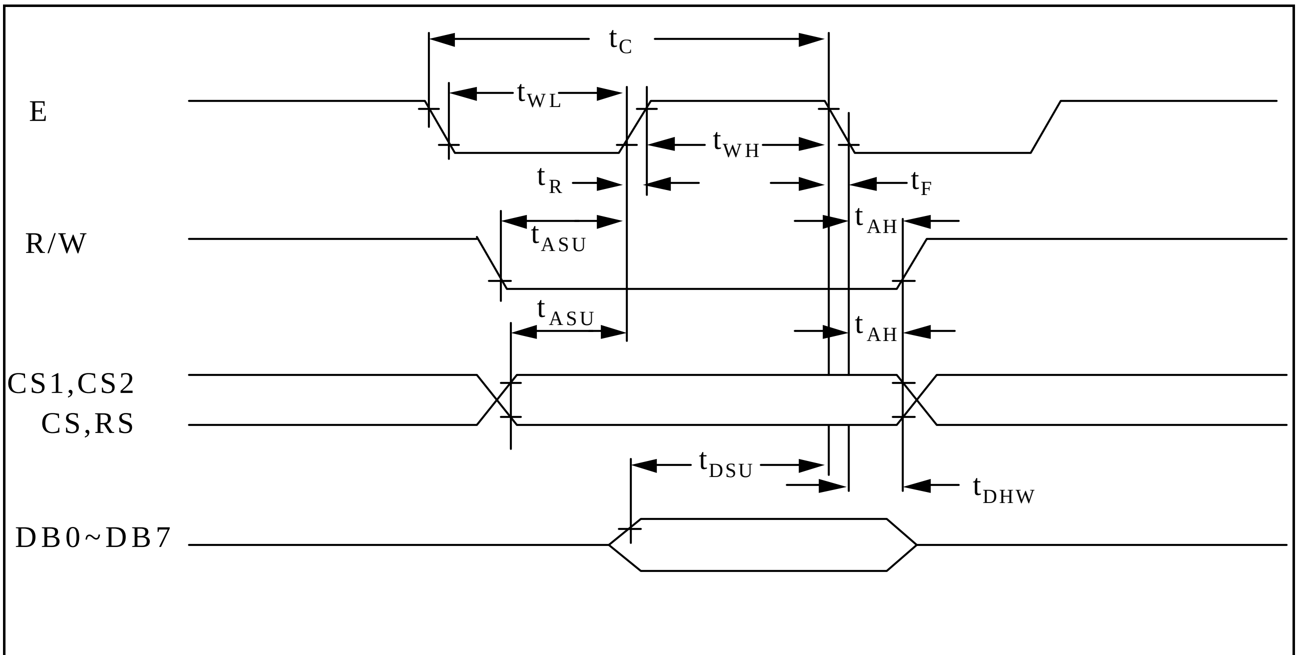
➢ Write or read cycle

Characteristic	Symbol	Min.	Typ.	Max.	Unit
E cycle	Tc	1000	-	-	ns
E high level width	Twh	450	-	-	ns
E low level width	Twl	450	-	-	ns
E rise time	Tr	-	-	25	ns
E fall time	Tf	-	-	25	ns
Address set-up time	Tasu	140	-	-	ns
Address hold time	Tah	10	-	-	ns
Data set-up time	Tdsu	200	-	-	ns
Data delay time	Td	-	-	320	ns
Data hold time (write)	Tdhw	10	-	-	ns
Data hold time (read)	Tdhr	20	-	-	ns

✧ Write timing



MPU Write timing

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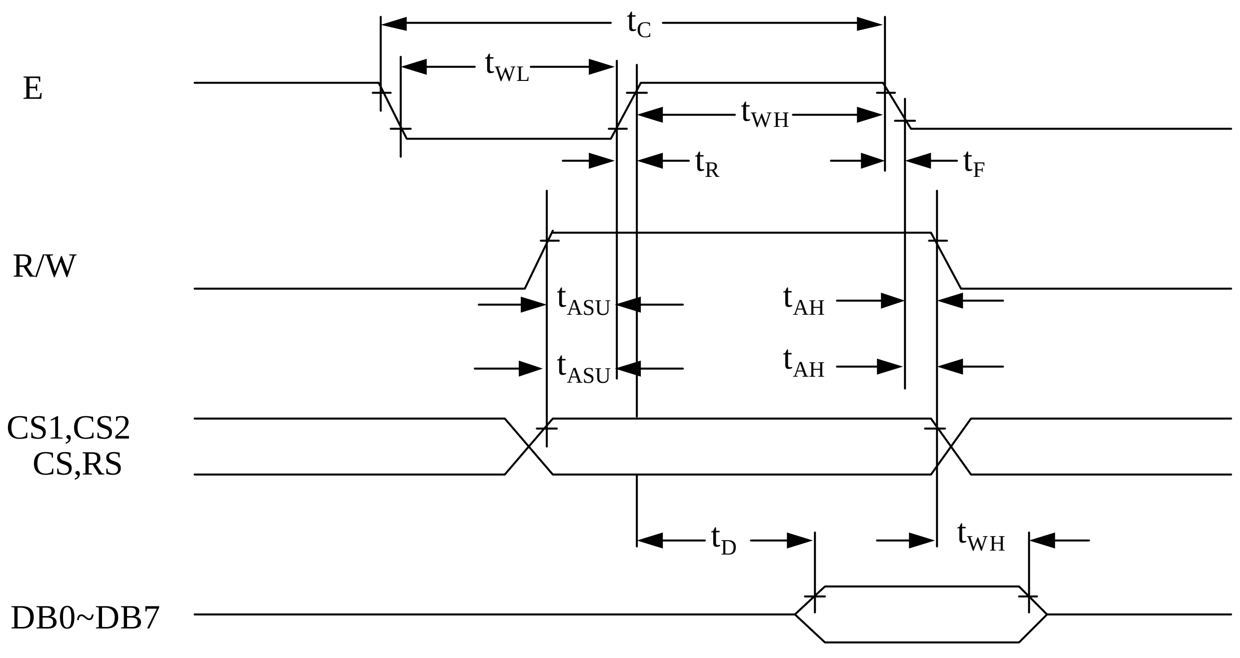
✧ Read timing



MPU Read timing

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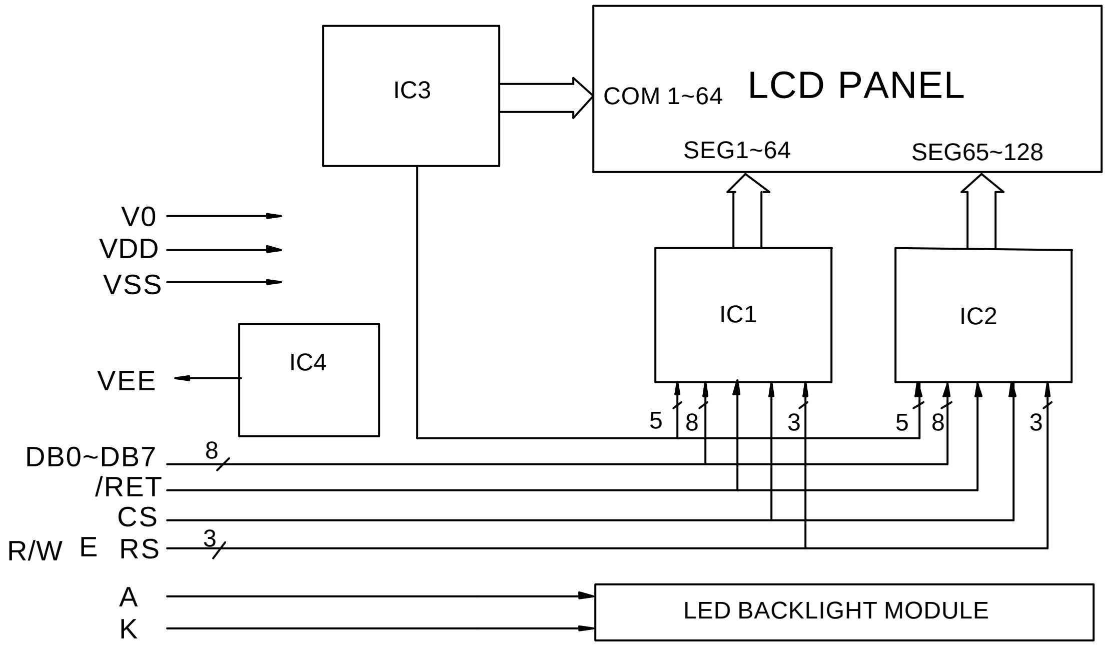
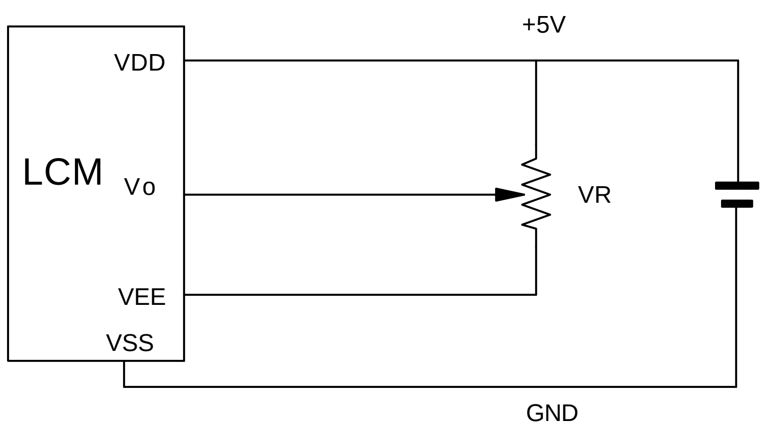
✧ Block diagram





VDD-Vo:LCD DRIVING VOLTAGE

VR:10K~20K

***Note**

1/64 duty, 1/9 bias

$V_{DD} \geqslant V1 \geqslant V2 \geqslant V3 \geqslant V4 \geqslant V5 > V_{EE}$

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✧ Display Control Instruction

The display control instructions control the internal state of the KS0108B. Instruction is received from MPU to KS0108B for the display control. The following table shows various instructions.

Instruction	RS	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Function
Read Display Data	1	1	Read data								Reads data (DB[7:0])from display data RAM to the data bus.
Write Display Data	1	0	Write data								Writes data (DB[7:0]) into display data RAM. After writing instruction, Y address is incriminated by 1 automatically
Status Read	0	1	Busy	0	ON/ OFF	Re- set	0	0	0	0	Reads the internal status BUSY 0: Ready 1: In operation ON/OFF 0: Display ON 1: Display OFF RESET 0: Normal 1: Reset
Set Address (Y address)	0	0	0	1	Y address (0~63)						Sets the Y address in the Y address counter
Set Display Start Line	0	0	1	1	Display start line (0~63)						Indicates the display data RAM displayed at the top of the screen.
Set Address (X address)	0	0	1	0	1	1	1	Page (0~7)			Sets the X address at the X address register.
Display On/off	0	0	0	0	1	1	1	1	1	0/1	Controls the display ON or OFF. The internal status and the DDRAM data is not affected. 0: OFF, 1: ON

1. Display On/Off

The display data appears when D is 1 and disappears when D is 0.
Though the data is not on the screen with D=0, it remains in the display data RAM.
Therefore, you can make it appear by changing D=0 into D=1.

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	1	1	1	1	D

2. Set Address (Y Address)

Y address (AC0~AC5) of the display data RAM is set in the Y address counter.
An address is set by instruction and increased by 1 automatically by read or write operations of display data.

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0

3. Set Page (X Address)

X address (AC0~AC2) of the display data RAM is set in the X address register.
Writing or reading to or from MPU is executed in this specified page until the next page is set.

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	0	1	1	1	AC2	AC1	AC0

4. Display Start Line (Z Address)

Z address (AC0~AC5) of the display data RAM is set in the display start line register and displayed at the top of the screen.
When the display duty cycle is 1/64 or others (1/32~1/64), the data of total line number of LCD screen, from the line specified by display start line instruction, is displayed.

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	1	AC5	AC4	AC3	AC2	AC1	AC0

5. Status Read

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	0	BUSY	0	ON/OFF	RESET	0	0	0	0

- BUSY
  When BUSY is 1, the Chip is executing internal operation and no instructions are accepted.
  When BUSY is 0, the Chip is ready to accept any instructions.
- ON/OFF
  When ON/OFF is 1, the display is on.
  When ON/OFF is 0, the display is off.
- RESET
  When RESET is 1, the system is being initialized.
  In this condition, no instructions except status read can be accepted.
  When RESET is 0, initializing has finished and the system is in the usual operation condition.

6. Write Display Data

Writes data (D0~D7) into the display data RAM.
After writing instruction, Y address is increased by 1 automatically.

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	0	D7	D6	D5	D4	D3	D2	D1	D0

7. Read Display Data

Reads data (D0~D7) from the display data RAM.
After reading instruction, Y address is increased by 1 automatically.

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	1	D7	D6	D5	D4	D3	D2	D1	D0

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✧ Operating principles & methods

1. I/O Buffer

Input buffer controls the status between the enable and disable of chip. Unless the CS1B to CS3 is in active mode, Input or output of data and instruction does not execute. Therefore internal state is not change. But RSTB and ADC can operate regardless CS!B-CS3.

2. Input register

Input register is provided to interface with MPU which is different operating frequency. Input register stores the data temporarily before writing it into display RAM.
When CS1B to CS3 are in the active mode, R/W and RS select the input register. The data from MPU is written into input register. Then writing it into display RAM. Data latched for falling of the E signal and write automatically into the display data RAM by internal operation.

3. Output register

Output register stores the data temporarily from display data RAM when CS1B, CS2B and CS3 are in active mode and R/W and RS=H, stored data in display data RAM is latched in output register. When CS1B to CS3 is in active mode and R/W=H , RS=L, status data (busy check) can read out.
To read the contents of display data RAM, twice access of read instruction is needed. In first access, data in display data RAM is latched into output register. In second access, MPU can read data which is latched. That is to read the data in display data RAM, it needs dummy read. But status read is not needed dummy read.

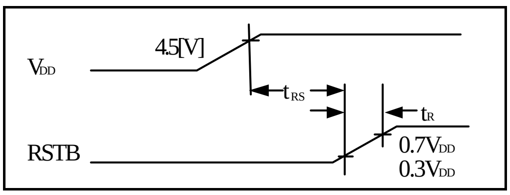
RS	R/W	Function
L	L	Instruction
	H	Status read (busy check)
H	L	Data write (from input register to display data RAM)
	H	Data read (from display data RAM to output register)

4. Reset

The system can be initialized by setting RSTB terminal at low level when turning power on, receiving instruction from MPU. When RSTB becomes low, following procedure is occurred.
1. Display off
2. Display start line register become set by 0. (Z-address 0)
While RSTB is low, No instruction except status read can by accepted. Therefore, execute other instructions after making sure that DB4= (clear RSTB) and DB7=0 (ready) by status read instruction.
The conditions of power supply at initial power up are shown in table 1.

Table 1. Power Supply Initial Conditions

Item	Symbol	Min	Typ	Max	Unit
Reset Time	t_{RS}	1.0	-	-	us
Rise Time	t_R	-	-	200	ns

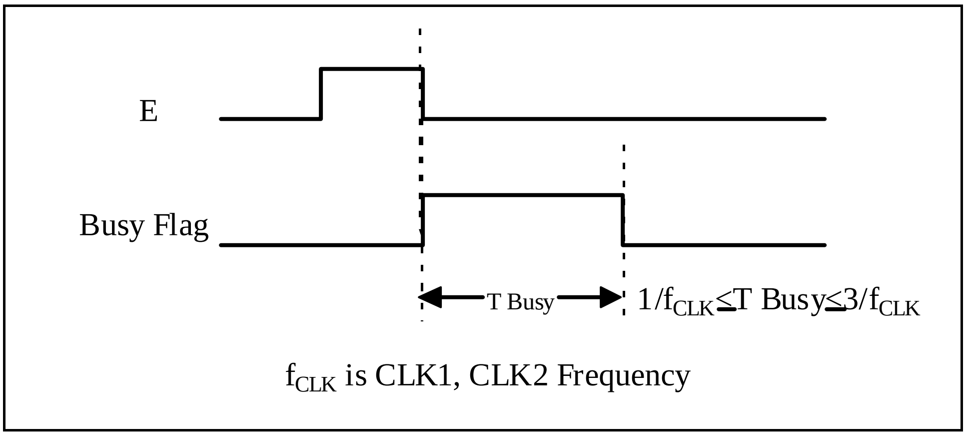


5. Busy flag

Busy flag indicates that KS0108B is operating or no operating. When busy flag is high, KS0108B is in internal operating .

When busy flag is low, KS0108B can accept the data or instruction.

DB7indicates busy flag of the KS0108B.



6. Display On/Off Flip-Flop

The display on/off flip-flop makes on/off the liquid crystal display. When flip-flop is reset (logical low), selective voltage or non-selective voltage appears on segment output terminals. When flip-flop is set (logic high), non selective voltage appears on segment output terminals regardless of display RAM data.

The display on/off flip-flop can changes status by instruction. The display data at all segments disappear while RSTB is low.

The status of the flip-flop is output to DB5 by status read instruction.

The display on/off flip-flop synchronized by CL signal.

7. X Page Register

X page register designates pages of the internal display data RAM.

Count function is not available. An address is set by instruction.

8. Y address counter

Y address counter designates address of the internal display data RAM. An address is set by instruction and is increased by 1 automatically by read or writes operations of display data.

9. Display Data RAM

Display data RAM stores a display data for liquid crystal display. To indicate on state dot matrix of liquid crystal display, write datra1. The other way, off state, writes 0.

Display data RAM address and segment output can be controlled by ADC signal.

ADC=H => Y-address 0: S1~Y address 63: S64

ADC=L => Y-address 0: S64~Yaddress 63: S1

ADC terminal connect the V_{DD} or V_{SS}.

10. Display Start Line Register

The display start line register indicates of display data RAM to display top line of liquid crystal display.

Bit data (DB<0.5>) of the display start line set instruction is latched in display start line register. Latched data is transferred to the Z address counter while FRM is high, presetting the Z address counter.

It is used for scrolling of the liquid crystal display screen.